

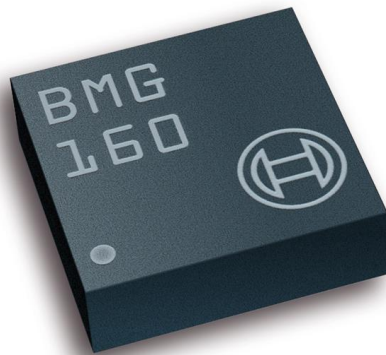
BMG160

Digital, triaxial gyroscope sensor

Bosch Sensortec



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BMG160: Data sheet

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BMG160

16BIT, DIGITAL, TRIAXIAL $\pm 125^\circ/\text{s}$ TO $\pm 2000^\circ/\text{s}$ GYROSCOPE SENSOR 3MM X 3MM X 0.95MM LGA PACKAGE

Key features

- 3-axis integrated gyroscope
- 16 bit digital resolution
- Switchable full-scale ranges: in total 5 ranges
- V_{DD} : 2.4 ... 3.6V / V_{DDIO} : 1.2 ... 3.6V
- Interrupt engine
- Low power consumption <5mA
- Short start-up time of 30ms
- Wake-up time in fast power-up mode only 10ms
- Operating temperature: -40°C ... $+85^\circ\text{C}$
- I²C and SPI interface (4-wire and 3-wire, SPI mode 0 and mode 3)
- Low-pass filters
- Fast and slow offset controller (FOC and SOC)
- Small footprint 12 pin LGA package, 3mm x 3mm x 0.95mm
- MSL level 1
- RoHS compliant, halogen-free, Pb-free
- Temperature Sensor

Typical applications

- Cell-phones
- Human machine interface devices
- Gaming
- Image stabilization
- Gesture recognition
- Indoor navigation

General Description

The BMG160 is a 3-axis angular rate sensor that is made of a surface micro machined sensing element and an evaluation ASIC.

Both parts are packed into one single LGA 3.0mm x 3.0mm x 0.95mm housing.

The BMG160 is designed to meet requirements for consumer applications such as image stabilization (DSC and camera-phone), gaming and pointing devices. It is capable to measure angular rates in three perpendicular room dimensions, the x-, y- and z-axis, and to provide the corresponding output signals. The BMG160 is fitted with digital bi-directional SPI and I²C interfaces for optimum system integration.

The BMG160 offers a variable V_{DDIO} voltage range from 1.2V to 3.6V and can be programmed to optimize functionality, performance and power consumption in customer specific applications. In addition it features an on-chip interrupt controller enabling motion-based applications without use of a microcontroller.

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1. Specification

If not stated otherwise, the given values are over lifetime and full performance temperature and voltage ranges, minimum/maximum values are $\pm 3\sigma$.

1.1 Electrical specification

Table 1: Electrical parameter specification

GYROSCOPE OPERATING CONDITIONS						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Supply Voltage Internal Domains	V_{DD}		2.4	3.0	3.6	V
Supply Voltage I/O Domain	V_{DDIO}		1.2	2.4	3.6	V
Voltage Input Low Level	V_{IL}	SPI & I ² C			$0.3V_{DDIO}$	-
Voltage Input High Level	V_{IH}	SPI & I ² C	$0.7V_{DDIO}$			-
Voltage Output Low Level	V_{OL}	$V_{DDIO} = 1.2V$ $I_{OL} = 3mA$, SPI & I ² C			$0.23V_{DDIO}$	-
Voltage Output High Level	V_{OH}	$V_{DDIO} = 1.2V$ $I_{OH} = 3mA$, SPI	$0.8V_{DDIO}$			-

1.2 Electrical and physical characteristics, measurement performance

Table 2: Electrical characteristics

GYROSCOPE OPERATING CONDITIONS						
Parameter	Symbol	Condition	Min	Typ	Max	Unit
Range	R_{FS125}	Selectable via serial digital interface		125		%/s
	R_{FS250}			250		%/s
	R_{FS500}			500		%/s
	R_{FS1000}			1,000		%/s
	R_{FS2000}			2,000		%/s

Supply Current in Normal Mode	I_{DD}	see ¹		5		mA
Supply Current in Fast Power-up Mode	I_{DDfpm}	see ¹		2.5		mA
Supply Current in Suspend - Mode	I_{DDsum}	see ¹ , digital and analog (only IF active)		25		μ A
Supply Current in Deep Suspend - Mode	I_{DDdsum}	see ¹		<5		μ A
Start-up time	t_{su}	to $\pm 1\%$ of final value; from power-off		30		ms
Wake-up time	t_{wusm}	From suspend- and deep suspend-modes		30		ms
Wake-up time	t_{wufpm}	From fast power-up mode		10		ms
Non-volatile memory (NVM) write-cycles	n_{NVM}				15	cycles
Operating Temperature	T_A	full performance	-40		+85	$^{\circ}$ C
Sensitivity		Ta=25 $^{\circ}$ C, R _{FS2000}		16.4		LSB/ $^{\circ}$ /s
		Ta=25 $^{\circ}$ C, R _{FS1000}		32.8		LSB/ $^{\circ}$ /s
		Ta=25 $^{\circ}$ C, R _{FS500}		65.6		LSB/ $^{\circ}$ /s
		Ta=25 $^{\circ}$ C, R _{FS250}		131.2		LSB/ $^{\circ}$ /s
		Ta=25 $^{\circ}$ C, R _{FS125}		262.4		LSB/ $^{\circ}$ /s
Sensitivity tolerance		Ta=25 $^{\circ}$ C, R _{FS2000}		± 1		%
Sensitivity Change over Temperature	TCS	Nominal V _{DD} supplies -40 $^{\circ}$ C \leq T _A \leq +85 $^{\circ}$ C R _{FS2000}		± 0.03		%/K

¹ Conditions of current consumption if not specified otherwise: TA=25 $^{\circ}$ C, BW_Gyro=1kHz, VDD=2.4V, VDDIO=1.8V, digital protocol on, no streaming data

Nonlinearity	NL	best fit straight line R_{FS1000}, R_{FS2000}		± 0.05		%FS
g- Sensitivity		Sensitivity to acceleration stimuli in all three axis (frequency <20kHz)			0.1	%/s/g
Zero-rate Offset	Off Ω_x Ω_y and Ω_z	Nominal V_{DD} supplies $T_A = 25^\circ\text{C}$, Slow and fast offset cancellation off		± 1		%/s
Zero- Ω Offset Change over Temperature	TCO	Nominal V_{DD} supplies $-40^\circ\text{C} \leq T_A \leq +85^\circ\text{C}$ R_{FS2000}		± 0.015		%/s per K
Output Noise	n_{rms}	rms, BW=47Hz (@ 0.014°/s/ $\sqrt{\text{Hz}}$)		0.1		%/s
Bandwidth BW	f_{-3dB}			unfiltered 230 116 64 47 32 23 12		Hz
Data rate (set of x,y,z rate)				2000 1000 400 200 100		Hz
Data rate tolerance(set of x,y,z rate)				± 0.3		%
Cross Axis Sensitivity		Sensitivity to stimuli in non-sense-direction		± 1		%
Temperature Sensor Measurement Range	T_s		-40		85	$^\circ\text{C}$



Temperature Sensor Slope	dT_s			0.5		K/LSB
Temperature Sensor Offset	OT_s			5 ± 3		K

2. Absolute maximum ratings

Table 3: Absolute maximum ratings

Parameter	Condition	Min	Max	Units
Voltage at Supply Pin (<1s)	V _{DD} Pin	-0.3	4.25	V
	V _{DDIO} Pin	-0.3	4.25	V
Voltage at any Logic Pin	Non-Supply Pin	-0.3	V _{DDIO} +0.3	V
Passive Storage Temp. Range	≤ 65% rel. H.	-50	+150	°C
None-volatile memory (NVM) Data Retention	T = 85°C, after 15 cycles	10		y
Mechanical Shock	Duration ≤ 200μs		10,000	g
	Duration ≤ 1.0ms		2,000	g
	Free fall onto hard surfaces		1.8	m
ESD	HBM, at any Pin		2	kV
	CDM		500	V
	MM		200	V

Note:

Stress above these limits may cause damage to the device. Exceeding the specified electrical limits may affect the device reliability or cause malfunction.

3. Block diagram

Figure 1 shows the basic building blocks of the BMG160:

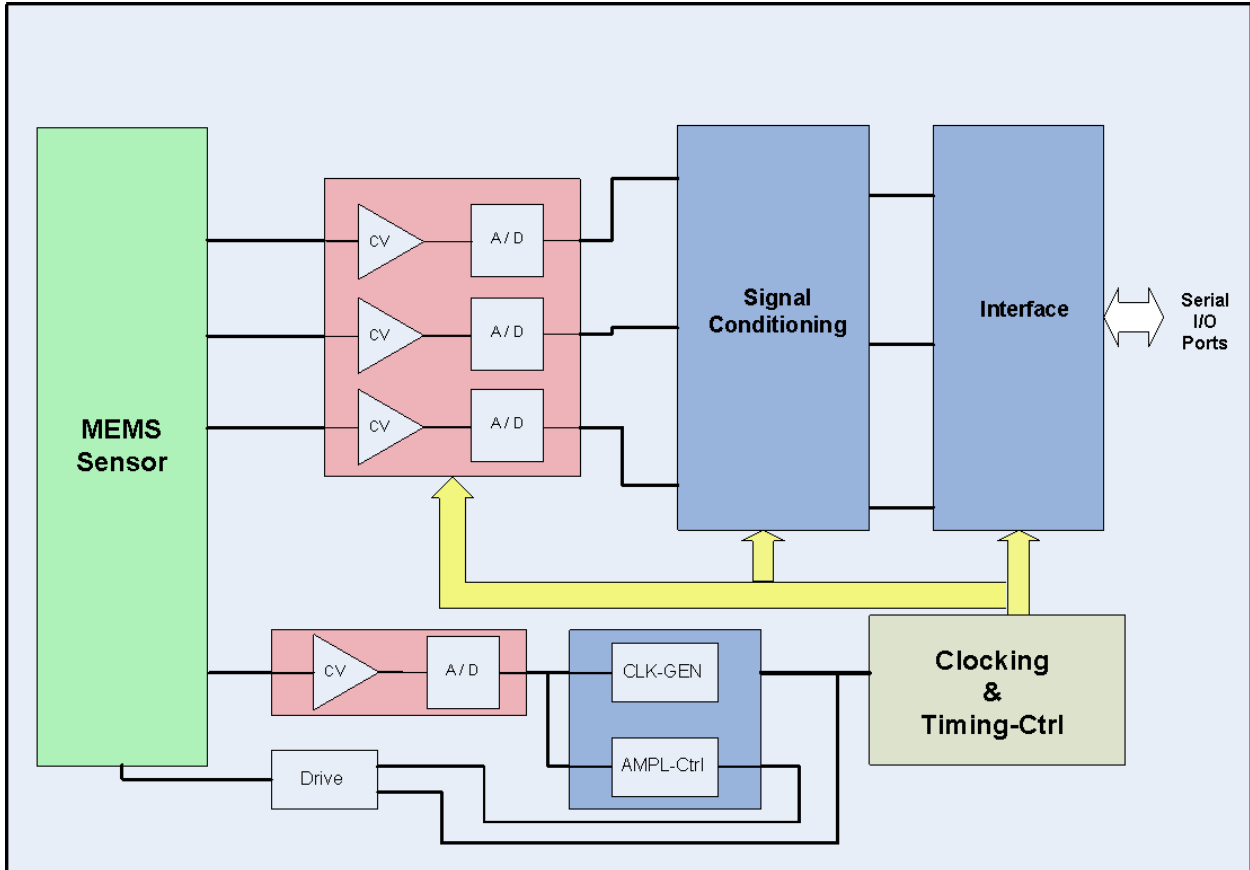


Figure 1: Block diagram of BMG160

4. Functional description

Note: Default values for registers can be found in chapter 6.

4.1 Supply voltage and power management

The BMG160 has two distinct power supply pins:

- V_{DD} is the main power supply for the internal blocks;
- V_{DDIO} is a separate power supply pin mainly used for the supply of the interface

For the switching sequence of power supply V_{DD} and V_{DDIO} it is recommended that V_{DD} is powered on and driven to the specified level before V_{DDIO} is powered ON. Otherwise there are no limitations on the voltage levels of both pins relative to each other, as long as each of them lies within its operating range. Furthermore, the device can be completely switched off ($V_{DD} = 0V$) while keeping the V_{DDIO} supply on ($V_{DDIO} > 0V$) or vice versa.

When the V_{DDIO} supply is switched off, all interface pins (CSB, SDI, SCK, PS) must be kept close to GND_{IO} potential.

The device contains a power-on reset (POR) generator. It resets the logic part and the register values after powering-on V_{DD} and V_{DDIO} . Please note, that all application specific settings which are not equal to the default settings (refer to 6.2 register map), must be re-set to their designated values after POR.

In case the I²C interface shall be used, a direct electrical connection between V_{DDIO} supply and the PS pin is needed in order to ensure reliable protocol selection. For SPI interface mode the PS pin must be directly connected to GND_{IO} .

4.2 Power modes

The BMG160 has 4 different power modes. Besides normal mode, which represents the fully operational state of the device, there are 3 energy saving modes: deep-suspend mode, suspend mode, and fast power up

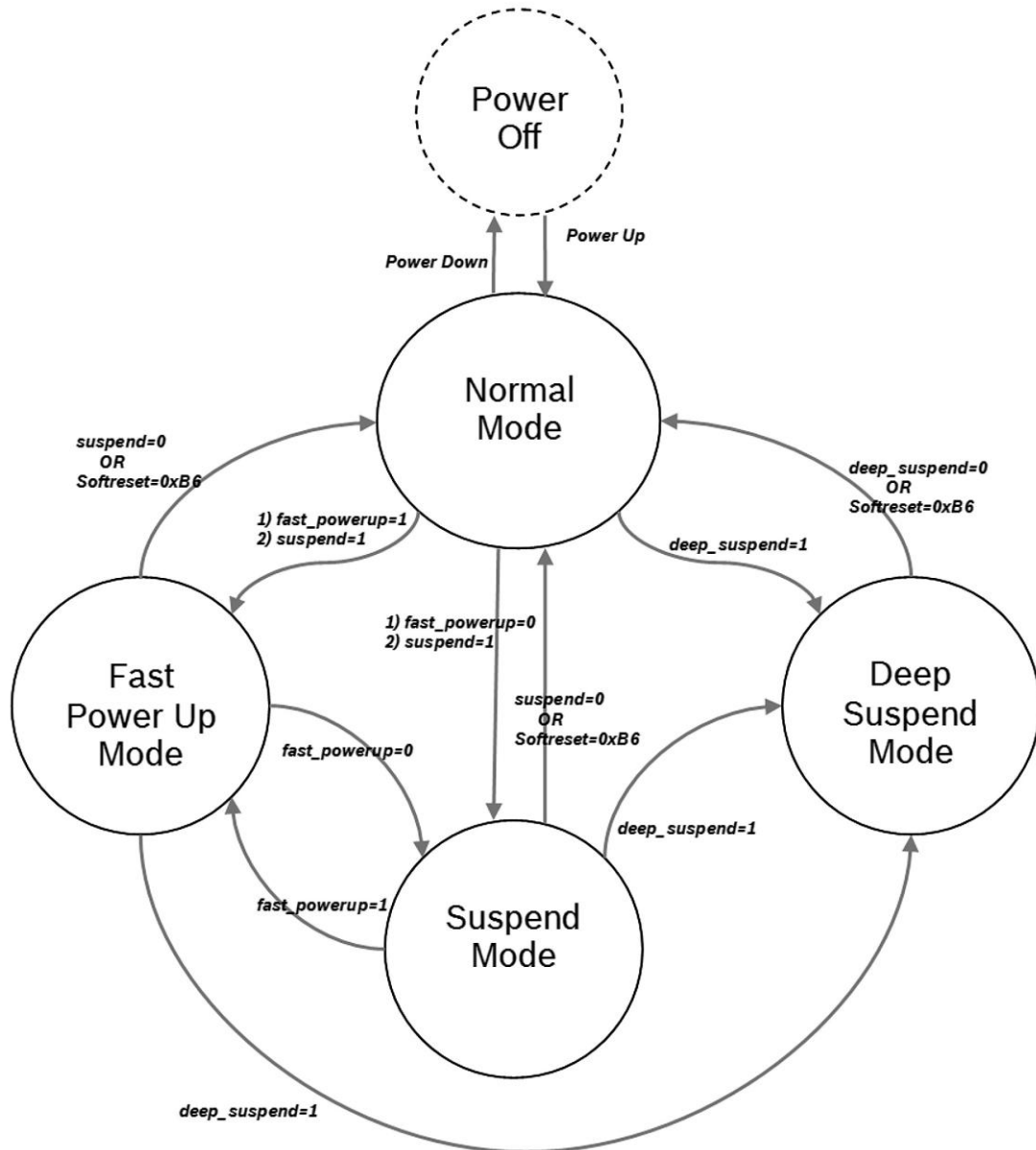


Figure 2: Block diagram of the power modes of BMG160

After power-up BMG160 is in normal mode so that all parts of the device are held powered-up and data acquisition is performed continuously.

In **deep-suspend mode** the device reaches the lowest possible power consumption. Only the interface section is kept alive. No data acquisition is performed and the content of the configuration registers is lost. Deep suspend mode is entered (left) by writing '1' ('0') to the (0x11) *deep_suspend* bit. The I²C watchdog timer remains functional. The (0x11) *deep_suspend* bit, the (0x34) *spi3* bit, (0x34) *i2c_wdt_en* bit and the (0x34) *i2c_wdt_sel* bit are functional in deep-suspend mode. Equally the interrupt level and driver configuration registers (0x20) *int1_lvl*, (0x20) *int1_od*, (0x20) *int2_lvl*, and (0x20) *int2_od* are accessible. Still it is possible to enter normal mode by writing to the (0x14) *softreset* register. Please note, that all application specific settings which are not equal to the default settings (refer to 6.2 register map), must be re-set to its designated values after leaving deep-suspend mode.

In **suspend mode** the whole analog part is powered down. No data acquisition is performed. While in suspend mode the latest rate data and the content of all configuration registers are kept. The only supported operations are reading registers as well as writing to the (0x14) *softreset* register.

Suspend mode is entered (left) by writing '1' ('0') to the (0x11) *suspend* bit. Bit (0x12) *fast_power_up* must be set to '0'.

Although write access to registers is supported at the full interface clock speed (SCL or SCK), a waiting period must be inserted between two consecutive write cycles (please refer also to section 7.2.1).

In **external wake-up mode**, when the device is in deep suspend mode or suspend mode, it can be woken-up by external trigger to Pin INT1/2. Register settings:

Table 4

ext_trig_sel<1:0>	Trigger source
'00'	No
'01'	INT1 pin
'10'	INT2 pin
'11'	SDO pin (SPI3 mode)

In **fast power-up mode** the sensing analog part is powered down, while the drive and the digital part remains operational. No data acquisition is performed. Reading and writing registers as well as writing to the (0x14) *softreset* register are supported without any restrictions. The latest rate data and the content of all configuration registers are kept. Fast power-up mode is entered (left) by writing '1' ('0') to the (0x11) *suspend* bit with bit (0x12) *fast_power_up* set to '1'.

4.2.1 Advanced power-saving modes

In addition to the power modes described in Figure 2, there are other advanced power modes that can be used to optimize the power consumption of the BMG160.

The *power_save_mode* is set by setting *power_save_mode*='1' (reg 0x12). This power mode implements a duty cycle and change between normal mode and fast-power-up mode. By setting the *sleep_dur* (time in ms in fast-power-up mode) (0x11 bits <1:3>) and *auto_sleep_dur*

(time in ms in normal mode) (0x12 bits <0:2>) different timings can be used. Some of these settings allow the sensor to consume less than 3mA. See also diagram below:

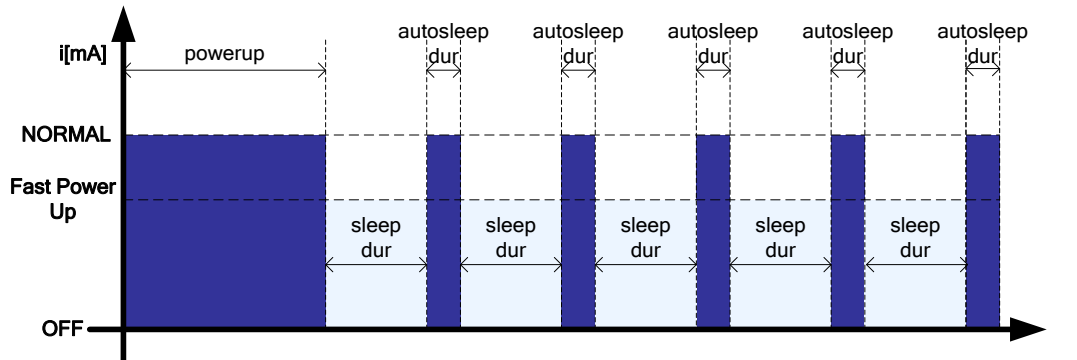


Figure 3: Duty-cycling

The possible configuration for the autosleep_dur and sleep_dur are indicated in the table below:

Table 5

sleep_dur<2:0>	Time (ms)
'000'	2 ms
'001'	4 ms
'010'	5 ms
'011'	8 ms
'100'	10 ms
'101'	15 ms
'110'	18 ms
'111'	20 ms

Table 6

autosleep_dur<2:0>	Time (ms)
'000'	Not allowed
'001'	4 ms
'010'	5 ms
'011'	8 ms
'100'	10 ms
'101'	15 ms
'110'	20 ms
'111'	40 ms

The only restriction for the use of the power save mode comes from the configuration of the digital filter bandwidth (reg 0x10). For each Bandwidth configuration, a minimum autosleep_dur must be ensured. For example, for Bandwidth=47Hz, the minimum autosleep_dur is 5ms. This is specified in the table below. For sleep_dur there is no restriction.

Table 7

bw<3:0>	Bandwidth (Hz)	Mini Autosleep_dur (ms)
'0111'	32 Hz	20 ms
'0110'	64 Hz	10 ms
'0101'	12 Hz	20 ms
'0100'	23 Hz	10 ms
'0011'	47 Hz	5 ms
'0010'	116 Hz	4 ms
'0001'	230 Hz	4 ms
'0000'	Unfiltered (523Hz)	4 ms

4.3 Sensor data

4.3.1 Rate data

The angular rate data can be read-out through addresses 0x02 through 0x07. The angular rate data is in 2's complement form according to Table 8 below. In order to not corrupt the angular rate data, the LSB should always be read out first. Once the LSB of the x,y, or z read-out registers have been read, the MSBs are locked until the MSBs are read out.

This default behavior can be switched off by setting the address 0x13 bit 6 (shadow_dis) = '1'. In this case there is no MSB locking, and the data is updated between each read.

The burst-access mechanism provides an efficient way to read out the angular rate data in I²C or SPI mode. During a burst-access, the BMG160 automatically increments the starting read address after each byte. Any address in the user space can be used as a starting address. When the address (0x3F – fifo_data) is reached, the address counter is stopped. In the user space address range, the 0x3F – fifo_data will be continuously read out until burst read ends. It is also possible to start directly with address 0x3F. In this case, the fifo_data (0x3F) data will be read out continuously. The burst-access allows data to be transferred over the I²C bus with an up to 50% reduced data density. The angular rate data in all read-out registers is locked as long as the burst read access is active. Reading the chip angular rate registers in burst read access mode ensures that the angular rate values in all readout registers belong to the same sample.

Table 8: Gyroscope Register Content for 16bit mode

Decimal value	Angular rate (in 2000°/s range mode)
+32767	+ 2000°/s
...	...
0	0°/s
...	...
-32767	- 2000°/s

Per default, the bandwidth of the data being read-out is limited by the internal low-pass filters according to the filter configuration. Unfiltered (high-bandwidth) data can be read out through the serial interface when the data_high_bw (0x13 bit 7) is set to '1'.

4.3.2 Temperature sensor

The width of temperature data is 8 bits given in two's complement representation. Temperature values are available in the (0x08) *temp* register.

The slope of the temperature sensor is 0.5K/LSB, its center temperature is 23°C [(0x08) *temp* = 0x00].

4.4 Angular rate read-out

Bandwidth configuration: The BMG160 processes the 2 kHz data out of the analog front end with a CIC/Decimation filter, followed by an IIR filter before sending this data to the interrupt handler. The possible decimation factors are 2, 5, 10 and 20. It is also possible to bypass these filters, and use the unfiltered 2 kHz data. The decimation factor / bandwidth of the filter can be set by setting the address space 0x10 bits<3:0> (bw<3:0>) as shown in the memory map section.

4.5 Self-test

A built-in self test (BIST) facility has been implemented which provides a quick way to determine if the device is operational within the specified conditions.

The BIST uses three parameters for evaluation of proper device operation:

- Drive voltage regulator
- Sense frontend offset regulator of x-,y- and z-channel
- Quad regulator for x-,y- and z-channel

If any of the three parameters is not within the limits the BIST result will be "Fail".

To trigger the BIST 'bit0' *bite_trig* in address 0x3C must be set '1'. When the test is performed, bit1 *bist_rdy* will be '1'. If the result is failed the bit *bist_failed* will be set to '1', otherwise stay a '0'.

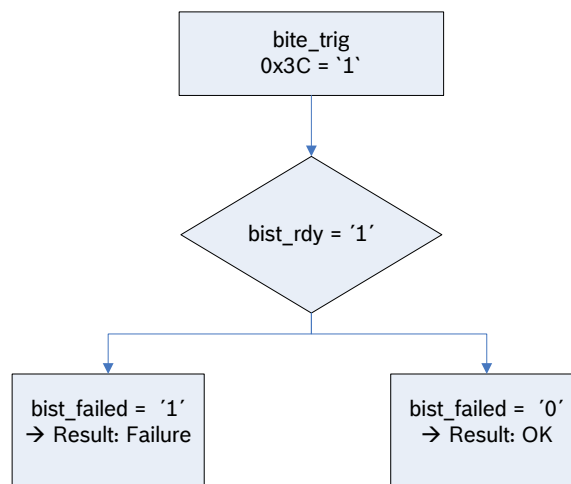


Figure 4: Flow Diagram

Another possibility to get information about the sensor status is to read out *rate_ok* 0x3C bit4. '1' indicates proper sensor function, no trigger is needed for this.

4.6 Offset compensation

Offsets in measured signals can have several causes but they are always unwanted and disturbing in many cases. Therefore, the BMG160 offers an advanced set of four digital offset compensation methods which are closely matched to each other. These are slow, fast, and manual compensation as well as inline calibration.

The compensation is performed with filtered data, and is then applied to both, unfiltered and filtered data. If necessary the result of this computation is saturated to prevent any overflow errors (the smallest or biggest possible value is set, depending on the sign). However, the registers used to read and write compensation values have a width of 8 bits.

The public offset compensation registers (0x36) to (0x39) are image of the corresponding registers in the NVM. With each image update (see section 4.6 Non-volatile memory for details) the contents of the NVM registers are written to the public registers. The public register can be over-written by the user at any time.

In case an internally computed compensation value is too small or too large to fit into the corresponding register, it is saturated in order to prevent an overflow error.

For every axes an offset up to 125°/s with 12 bits full resolution can be calibrated (resolution 0.06°/s).

The modes will be controlled using SPI/I2C commands.

By writing '1' to the (0x21) *offset_reset* bit, all dynamic (fast & slow) offset compensation registers are reset to zero.

4.6.1 Slow compensation

In slow regulation mode, the rate data is monitored permanently. If the rate data is above 0°/s for a certain period of time, an adjustable rate is subtracted by the offset controller. This procedure of monitoring the rate data and subtracting of the adjustable rate at a time is repeated continuously. Thus, the output of the offset converges to 0°/s.

The slow regulation can be enabled through the *slow_offset_en_x/y/z* (0x31 <0:2>) bits for each axis. The slow offset cancellation will work for filtered and unfiltered data (*slow_offset_unfilt* (0x1A <5>); *slow_offset_unfilt*=1 → unfiltered data are selected)

Slow Offset cancellation settings are the adjustable rate (*slow_offset_th* 0x31 <7:6>) and the time period (*slow_offset_dur* 0x31 <5:3>)

4.6.2 Fast compensation

A fast offset cancellation controller is implemented in BMG160. The fast offset cancellation process is triggerable via SPI/I2C.

The fast offset cancellation can be enabled through the *fast_offset_en_x/y/z* (0x32 <0:2>) bits for each axis. The enable bits will not start the fast offset cancellation! The fast offset cancellation has to be started by setting the *fast_offset_en* (0x32 <3>) bit. Afterwards the algorithm will start and if the algorithm is finished the *fast_offset_en* (0x32 <3>) will be reset to 0.



The fast offset cancellation will work for filtered and unfiltered data (fast_offset_unfilt (0x1B <7>); fast_offset_unfilt=1 → unfiltered data are selected)
The fast offset cancellation parameters are fast_offset_wordlength (0x32 <5:4>)

The sample rate for the fast offset cancellation corresponds to the sample rate of the selected bandwidth. For unfiltered data and bandwidth settings 0-2 the sample rate for the fast offset cancellation will be 400Hz.

The resolution of the calculated offset values for the fast offset compensation depends on the range setting being less accurate for higher range (e.g. range=2000°/s). Therefore we recommend a range setting of range=125°/s for fast offset compensation.

4.6.3 Manual compensation

The contents of the public compensation registers (0x36 ... 0x39) *offset_x/y/z* can be set manually via the digital interface. It is recommended to write into these registers directly after a new data interrupt has occurred in order not to disturb running offset computations.

Writing to the offset compensation registers is not allowed while the fast compensation procedure is running.

4.6.4 Inline calibration

For certain applications, it is often desirable to calibrate the offset once and to store the compensation values permanently. This can be achieved by using one of the aforementioned offset compensation methods to determine the proper compensation values and then storing these values permanently in the NVM. See section 4.7 Non-volatile memory for details of the storing procedure.

Each time the device is reset, the compensation values are loaded from the non-volatile memory into the image registers and used for offset compensation until they are possibly overwritten using one of the other compensation methods.

4.7 Non-volatile memory

The entire memory of the BMG160 consists of three different kinds of registers: hard-wired, volatile, and non-volatile. Part of it can be both read and written by the user. Access to non-volatile memory is only possible through (volatile) image registers.

Altogether, there are eight registers (octets) with NVM backup which are accessible by the user. The addresses of the image registers range from 0x36 to 0x3B. While the addresses up to 0x39 are used for offset compensation (see 4.4 Offset Compensation), addresses 0x3A and 0x3B are general purpose registers not linked to any sensor-specific functionality.

The content of the NVM is loaded to the image registers after a reset (either POR or softreset) or after a user request which is performed by writing '1' to the write-only bit (0x33) *nvm_load*. As long as the image update is in progress, bit (0x33) *nvm_rdy* is '0', otherwise it is '1'. In order to read out the correct values (after NVM loading) waiting time is min. 1ms.

The image registers can be read and written like any other register.

Writing to the NVM is a three-step procedure:

1. Write the new contents to the image registers.
2. Write '1' to bit (0x33) *nvm_prog_mode* in order to unlock the NVM.
3. Write '1' to bit (0x33) *nvm_prog_trig* and keep '1' in bit (0x33) *nvm_prog_mode* in order to trigger the write process.

Writing to the NVM always renews the entire NVM contents. It is possible to check the write status by reading bit (0x33) *nvm_rdy*. While (0x33) *nvm_rdy* = '0', the write process is still in progress; if (0x33) *nvm_rdy* = '1', then writing is completed. As long as the write process is ongoing, no change of power mode and image registers is allowed. Also, the NVM write cycle must not be initiated while image registers are updated, in suspend mode.

Please note that the number of permitted NVM write-cycles is limited as specified in Table 2. The number of remaining write-cycles can be obtained by reading bits (0x33) *nvm_remain*.

4.8 Interrupt controller

The BMG160 is equipped with 3 programmable interrupt engines. Each interrupt can be independently enabled and configured. If the trigger condition of an enabled interrupt is fulfilled, the corresponding status bit is set to '1' and the selected interrupt pin is activated. The BMG160 provides two interrupt pins, INT1 and INT2; interrupts can be freely mapped to any of these pins. The state of a specific interrupt pin is derived from a logic 'or' combination of all interrupts mapped to it.

The interrupt status registers are updated when a new data word is written into the rate data registers. If an interrupt is disabled, all active status bits associated with it are immediately reset.

Gyro Interrupts are fully functional in normal mode, only. Interrupts are limited in their functionality in other operation modes. Please contact our technical support for further assistance.

4.8.1 General features

An interrupt is cleared depending on the selected interrupt mode, which is common to all interrupts. There are three different interrupt modes: non-latched, latched, and temporary. The mode is selected by the (0x21) *latch_int* bits according to Table 9.

Table 9: Interrupt mode selection

(0x21) <i>latch_int</i>	Interrupt mode
0000b	non-latched
0001b	temporary, 250ms
0010b	temporary, 500ms
0011b	temporary, 1s
0100b	temporary, 2s
0101b	temporary, 4s
0110b	temporary, 8s
0111b	latched
1000b	non-latched
1001b	temporary, 250µs
1010b	temporary, 500µs
1011b	temporary, 1ms
1100b	temporary, 12.5ms
1101b	temporary, 25ms
1110b	temporary, 50ms
1111b	latched

An interrupt is generated if its activation condition is met. It can not be cleared as long as the activation condition is fulfilled. In the non-latched mode the interrupt status bit and the selected pin (the contribution to the 'or' condition for INT1 and/or INT2) are cleared as soon as the

activation condition is no more valid. Exception to this behavior is the new data interrupt, which is automatically reset after a fixed time.

In latched mode an asserted interrupt status and the selected pin are cleared by writing '1' to bit (*0x21*) *reset_int*. If the activation condition still holds when it is cleared, the interrupt status is asserted again with the next change of the rate registers.

In the temporary mode an asserted interrupt and selected pin are cleared after a defined period of time. The behaviour of the different interrupt modes is shown graphically in Figure 5. The timings in this mode are subject to the same tolerances as the bandwidths (see Table 2).

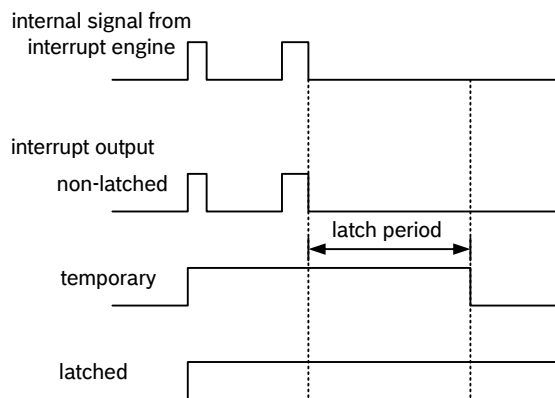


Figure 5: Interrupt modes

4.8.2 Mapping to physical interrupt pins (inttype to INT Pin#)

Registers (*0x17*) to (*0x19*) are dedicated to mapping of interrupts to the interrupt pins "INT1" or "INT2". Setting (*0x17*) *int1_*"inttype" to '1' ('0') maps (unmaps) "inttype" to pin "INT1". Correspondingly setting (*0x19*) *int2_*"inttype" to '1' ('0') maps (unmaps) "inttype" to pin "INT2".

Note: "inttype" has to be replaced with the precise notation, given in the memory map in chapter 6.

4.8.3 Electrical behaviour (INT pin# to open-drive or push-pull)

Both interrupt pins can be configured to show the desired electrical behaviour. The 'active' level of each interrupt pin is determined by the $(0x16)$ *int1_lvl* and $(0x16)$ *int2_lvl* bits.

If $(0x16)$ *int1_lvl* = '1' ('0') / $(0x16)$ *int2_lvl* = '1' ('0'), then pin "INT1" / pin "INT2" is active '1' ('0'). The characteristic of the output driver of the interrupt pins may be configured with bits $(0x16)$ *int1_od* and $(0x16)$ *int2_od*. By setting bits $(0x16)$ *int1_od* / $(0x16)$ *int2_od* to '1', the output driver shows open-drive characteristic, by setting the configuration bits to '0', the output driver shows push-pull characteristic. When open-drive characteristic is selected in the design, external pull-up or pull-down resistor should be applied according the *int_lvl* configuration.

4.8.4 New data interrupt

This interrupt serves for synchronous reading of angular rate data. It is generated after storing a new value of z-axis angular rate data in the data register. The interrupt is cleared automatically after 280-400 μ s (depending on Interrupt settings).

The interrupt mode of the new data interrupt is fixed to non-latched.

It is enabled (disabled) by writing '1' ('0') to bit $(0x15)$ *data_en*. The interrupt status is stored in bit $(0x0A)$ *data_int*.

4.8.5 Any-motion detection / Interrupt

Any-motion (slope) detection uses the slope between successive angular rate signals to detect changes in motion. An interrupt is generated when the slope (absolute value of angular rate difference) exceeds a preset threshold. It is cleared as soon as the slope falls below the threshold. The principle is made clear in Figure 6.

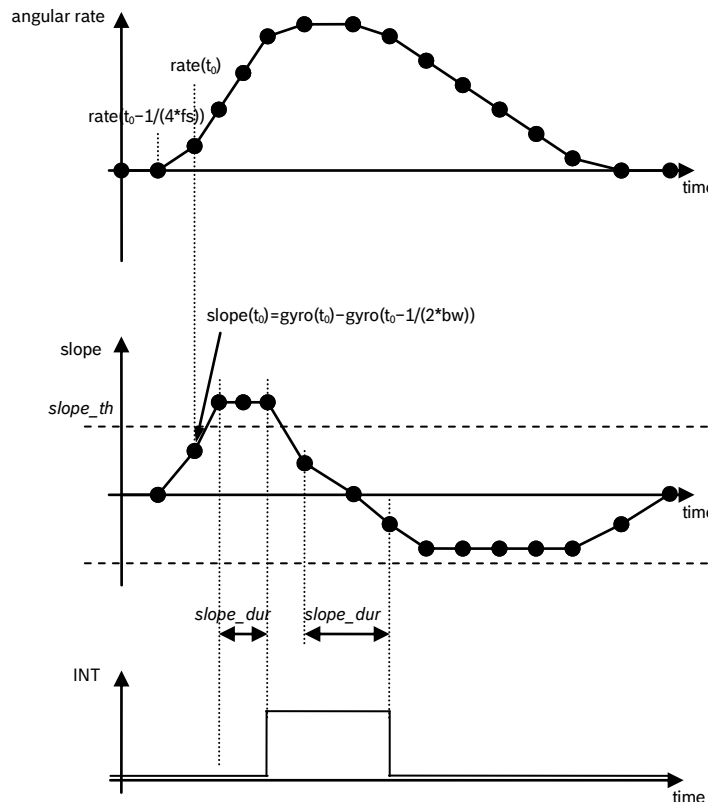


Figure 6 : Principle of any-motion detection

The threshold is defined through register (0x1B) *any_th*. In terms of scaling 1 LSB of (0x1B) *any_th* corresponds to 1 °/s in 2000°/s-range (0.5°/s in 1000°/s-range, 0.25°/s in 500°/s -range ...). Therefore the maximum value is 125°/s in 2000°/s-range (62.5°/s 1000°/s-range, 31.25 in 500°/s -range ...).

The time difference between the successive angular rate signals depends on the selected update rate(*fs*) which is coupled to the bandwidth and equates to $1/(4*fs)$ ($t=1/(4*fs)$). For bandwidth settings with an update rate higher than 400Hz (bandwidth =0,1,2) *fs* is set to 400Hz.

In order to suppress false triggers, the interrupt is only generated (cleared) if a certain number *N* of consecutive slope data points is larger (smaller) than the slope threshold given by (0x1B) *any_th*. This number is set by the (0x1C) *any_dursample* bits. It is $N = [(0x1C) any_dursample + 1]*4$ for (0x1C). *N* is set in samples. Thus the time is scaling with the update rate (*fs*).

Example: (0x1C) *slope_dur* = 00b, ..., 11b = 4 samples, ..., 16 samples.

4.8.5.1 Enabling (disabling) for each axis

Any-motion detection can be enabled (disabled) for each axis separately by writing '1' ('0') to bits (0x1C) *any_en_x*, (0x1C) *any_en_y*, (0x1C) *any_en_z*. The criteria for any-motion detection are fulfilled and the Any-Motion interrupt is generated if the slope of any of the enabled axes exceeds the threshold (0x1B) *any_th* for [(0x1C) *slope_dur* +1]*4 consecutive times. As soon as the slopes of all enabled axes fall or stay below this threshold for [(0x1C) *slope_dur* +1]*4 consecutive times the interrupt is cleared unless interrupt signal is latched.

4.8.5.2 Axis and sign information of slope / any motion interrupt

The interrupt status is stored in bit (0x09) *any_int*. The Any-motion interrupt supplies additional information about the detected slope. The axis which triggered the interrupt is given by that one of bits (0x0B) *any_first_x*, (0x0B) *any_first_y*, (0x0B) *any_first_z* that contains a value of '1'. The sign of the triggering slope is held in bit (0x0B) *any_sign* until the interrupt is retriggered. If (0x0B) *slope_sign* = '1' ('0'), the sign is positive (negative).

4.8.6 High-Rate interrupt

This interrupt is based on the comparison of angular rate data against a high-rate threshold for the detection of shock or other high-angular rate events. The principle is made clear in Figure 7 below:

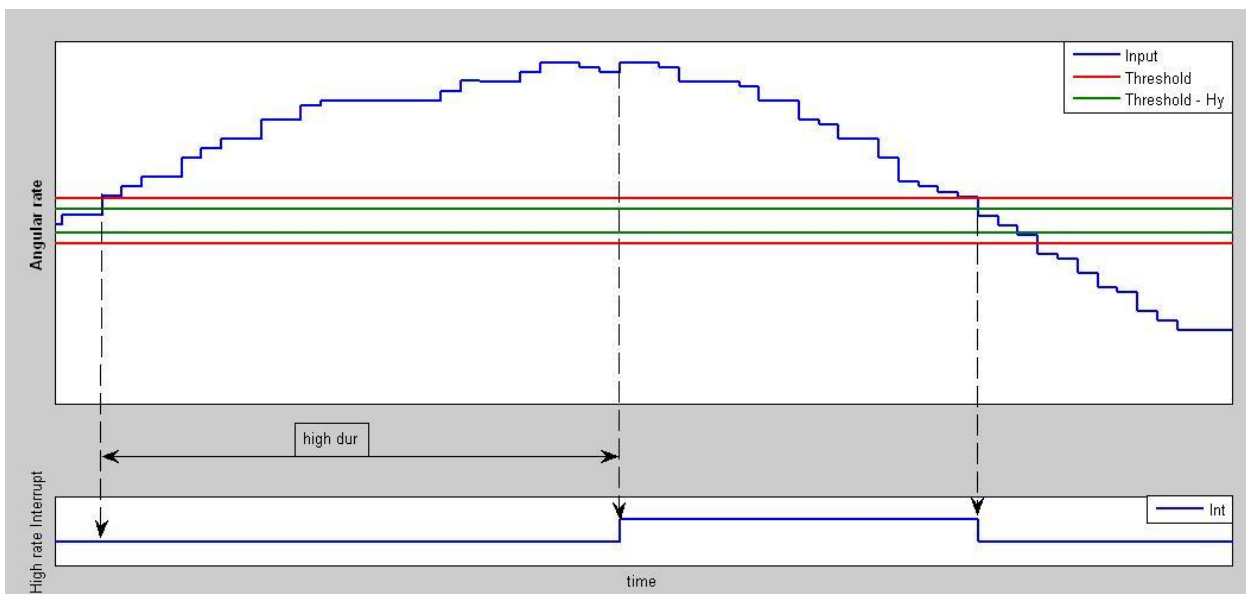


Figure 7

The high-rate interrupt is enabled (disabled) per axis by writing '1' ('0') to bits (0x22) *high_en_x*, (0x24) *high_en_y*, and (0x26) *high_en_z*, respectively. The high-rate threshold is set through the (0x22) *high_th_x* register, (0x24) *high_th_y* register and (0x26) *high_th_z* for the corresponding axes. The meaning of an LSB of (0x22/24/26) *high_th_x/y/z* depends on the selected °/s-range: it corresponds to 62.5°/s in 2000°/s-range, 31.25°/s in 1000°/s-range, 15.625°/s in 500°/s -range ...). The *high_th_x/y/z* register setting 0 corresponds to 62.26°/s in 2000°/s-range, 31.13°/s in 1000°/s-range, 15.56°/s in 500°/s-range ...). Therefore the maximum value is 1999.76°/s in 2000°/s-range (999.87°/s 1000°/s-range, 499.93°/s in 500°/s -range ...).

A hysteresis can be selected by setting the (0x22/24/26) *high_hy_x/y/z* bits. Analogously to (0x22/24/26) *high_th_x/y/z*, the meaning of an LSB of (0x22/24/26) *high_hy_x/y/z* bits is °/s-range dependent: The *high_hy_x/y/z* register setting 0 corresponds to an angular rate difference of 62.26°/s in 2000°/s-range, 31.13°/s in 1000°/s-range, 15.56°/s in 500°/s-range The meaning of an LSB of (0x22/24/26) *high_hy_x/y/z* depends on the selected °/s-range too: it corresponds to 62.5°/s in 2000°/s-range, 31.25°/s in 1000°/s-range, 15.625°/s in 500°/s -range ...).

The high-rate interrupt is generated if the absolute value of the angular rate of at least one of the enabled axes ('or' relation) is higher than the threshold for at least the time defined by the (0x23/25/27) *high_dur_x/y/z* register. The interrupt is reset if the absolute value of the angular rate of all enabled axes ('and' relation) is lower than the threshold minus the hysteresis. In bit (0x09) *high_int* the interrupt status is stored. The relation between the content of (0x23/25/27) *high_dur_x/y/z* and the actual delay of the interrupt generation is $\text{delay [ms]} = [(0x23/25/27) \text{ high_dur_x/y/z} + 1] \cdot 2.5 \text{ ms}$. Therefore, possible delay times range from 2.5 ms to 640 ms.

4.8.6.1 Axis and sign information of high-rate interrupt

The axis which triggered the interrupt is indicated by bits (0x0C) *high_first_x*, (0x0C) *high_first_y*, and (0x0C) *high_first_z*. The bit corresponding to the triggering axis contains a '1' while the other bits hold a '0'. These bits are cleared together with clearing the interrupt status. The sign of the triggering angular rate is stored in bit (0x0C) *high_sign*. If (0x0C) *high_sign* = '1' ('0'), the sign is positive (negative).

5. FIFO Operation

5.1 FIFO Operating Modes

The BMG160 features an integrated FIFO memory capable of storing up to 100 frames of data in FIFO mode. Each frame consists of three 16-bit rate_{x,y,z} data words, and 16 bits of interrupt data sampled at the same point in time. The FIFO is a buffer memory which can be configured to operate in the following modes:

- FIFO Mode:** In FIFO mode the X, Y, and Z rate data are stored in the buffer memory. A watermark interrupt can be enabled, which is triggered when the buffer is filled to a configurable level. The buffer will be continuously filled up until the last slot. When the buffer is full the data collection is stopped, and all additional samples are ignored. The buffer has a depth of 100 frames.
- STREAM Mode:** In STREAM mode the X, Y, and Z rate data is stored in the buffer until it is full. The buffer has a depth of 99 frames. When the buffer is full the data collection continues and old data are discarded in a wrap-around manner. A watermark interrupt can be enabled, which is triggered when the buffer is filled to a configurable level.
- BYPASS Mode:** In bypass mode, only the current sensor data can be read out from the FIFO address. Essentially, the FIFO behaves like the STREAM mode with a depth of 1.

The FIFO operating mode is selected with the address 0x3E bits<7:6> (mode<1:0>) according to Table 10. Register mode<1:0> will always contain the current operating mode. Writing to the mode<1:0> register clears / resets the buffer.

Table 10: FIFO operating mode selection

Address: 0x3E bits<7:6> mode<1:0>	FIFO Mode	Function
'00' (Default)	BYPASS	buffer depth of 1 frame; old data are discarded
'01'	FIFO	data collection stops when buffer is full (100 frames)
'10'	STREAM	when buffer full: sampling continues, old data discarded
'11'	reserved	

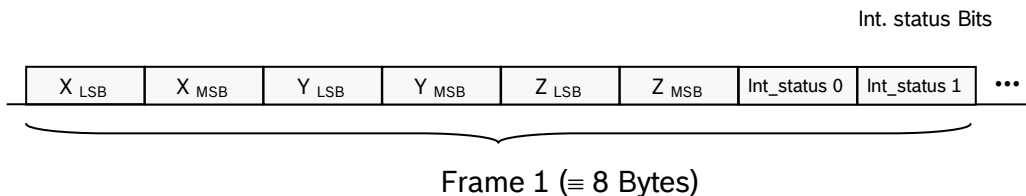
5.2 FIFO Data Readout

The FIFO stores the data that are also available at the addresses 0x07 – 0x02 (gyro readout registers rate_x,y,z_msb,lsb). Thus, all configuration settings apply to the FIFO data as well as to the gyro data readout registers. The FIFO can be read out from the address 0x3F bits<7:0> (fifo_data<7:0>). The readout can be performed by using burst mode. During burst mode readout from register fifo_data<7:0>, the read address counter is not incremented, effectively trapping the address counter. The trapping will also happen if burst read starts at addresses below the fifo_data<7:0> register. A single burst can read out one or more frames at a time. If a frame is not read completely due to an incomplete read operation, the remaining part of the frame is lost. In this case the FIFO aligns to the next frame during the next read operation. The address 0x3E bits<1:0> (data_select<1:0>) allows the user to select the data stored in the FIFO according to Table 11. Writing to data_select<1:0> clears the FIFO buffer.

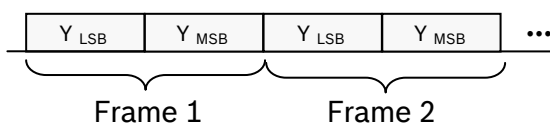
Table 11: FIFO data selection

Address: 0x3E bits<1:0> data_select	data of axis stored in FIFO
'00' (Default)	X,Y,Z
'01'	X only
'10'	Y only
'11'	Z only
Address: 0x3D bit 7 tag	Interrupt data stored in FIFO
'0' Default)	Do not collect Interrupts
'1'	collect Interrupts

If all axes and tag are enabled, the format of the data read-out from register fifo_data<7:0> is as follows:



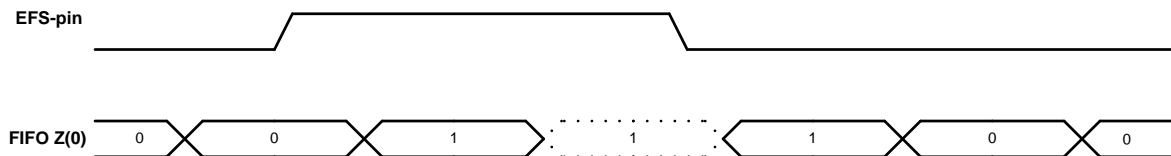
If only one axis is enabled (and tag is disabled), the format of the data read-out from register fifo_data<7:0> is as follows (example shown: Y-axis only, other axis are equivalent). The buffer depth of the FIFO is independent of the fact whether all or a single axis have been selected.



5.2.1 External FIFO synchronization (EFS) for the gyroscope

In addition to the explained data format for the angular rate and interrupt data, the FIFO of the gyroscope features a mode that allows the precise synchronization of external event with the gyroscope angular rate and gyroscope interrupts saved in the internal FIFO. This synchronization can be used for example for image and video stabilization applications. The EFS Mode can be used in the operating modes FIFO-Mode and STREAM-Mode but not in BYPASS-Mode.

In order to use the EFS capability, any of the gyroscope interrupt pins (INT1 or INT2) can be reconfigured to act as EFS-pin, but not both. In addition, the EFS-Mode has to be enabled. The so configured interrupt pin will then behave as an input pin and not as an interrupt pin. The working principle is shown in below figure:



Timing diagram for external FIFO synchronization. EFS-pin is the Interrupt pin configured as EFS-Mode. FIFO z(0) is the least significant bit of the z-axis gyro data stored in the FIFO.

In order to enable the EFS-Mode the register (0x34) bit<5> must be set to “1”. To select the INT2 pin as EFS-pin, set the register (0x34) bit<4> to “1”. To select the INT1 pin as EFS-pin, set the register (0x34) bit<4> to “0”.

In this Mode, the least significant bit of the z-axis is used as tag-bit, therefore losing its meaning as gyroscope data bit. The remaining 15 bits of the z-axis gyroscope data keep the same meaning as in standard mode.

Once the EFS-pin is set to high level, the next FIFO word will be marked with an EFS-tag (z-axis LSB = 1). While the EFS-pin is kept at a High level, the corresponding FIFO words would be always marked with an EFS-tag. After the EFS-pin is reset to low level, the immediate next FIFO word could still be marked with the EFS-tag and only after this word, the next EFS-tag will be reset (z-axis LSB=0). This is shown in the above diagram.

The EFS-tag synchronizes external events with the same time precision as the FIFO update rate. Therefore update rate of the EFS-tag is determined by the output data rate and can be set from 100Hz up to 2,000Hz. For more information consult the register (0x10) (BW) in the register description.



5.2.2 Interface speed requirements for FIFO use

In order to use the FIFO effectively, larger blocks of data need to be read out quickly. Depending on the output data rate of the sensor, this can impose requirements on the interface.

The output data rate of the BMG160 is determined by the filter configuration (see chapter 6.2). What interface speed is required depends on the selected rate.

- For an I²C speed of 400 kHz, every filter mode can be used.
- For an I²C speed of 200 kHz, only modes with an output data rate of 1 KHz and below are recommended.
- For an I²C speed of 100 kHz, only modes with an output data rate of 400 Hz and below are recommended.

5.2.3 FIFO Frame Counter and Overrun Flag

The address 0x0E bits<6:0> (frame_counter<6:0>) indicate the current fill level of the buffer. If additional frames are written to the buffer although the FIFO is full, the address 0x0E bit 7 (overrun flag) is set. If the FIFO is reset, the FIFO fill level indicated in the frame_counter<6:0> is set to '0' and the overrun flag is reset each time a write operation happens to the FIFO configuration registers. The overrun bit is not reset when the FIFO fill level frame_counter<6:0> has decremented to '0' due to reading from the fifo_data<7:0> register.



5.2.4 FIFO Interrupts

The FIFO controller has the capability to issue two different interrupt events, the FIFO-full and the watermark event. Generally the FIFO-full and watermark interrupts are functional in all non-composite modes, including BYPASS. They are not functional. The watermark interrupt is asserted when the fill level in the buffer has reached the frame number defined by the `h2o_mrk_lvl_trig_ret<6:0>` register. In order to enable the watermark interrupt, the `fifo_en` bit `fifo_wm_en`, as well as one or both of the `int1_fifo` or `int2_fifo` bits must be set. The status of the watermark interrupt may be read back through the address `0x0A` bit 4 (`fifo_int`) status bit. Writing to the `h2o_mrk_lvl_trig_ret<6:0>` register clears the FIFO buffer.

The FIFO-full interrupt is the second interrupt capability associated with the FIFO. The FIFO-full interrupt is asserted when the buffer has been fully filled with samples. In FIFO mode this occurs 100 samples, in STREAM mode 99 samples, and in BYPASS mode 1 sample after the buffer has been cleared. In order to enable the watermark interrupt, the `fifo_en` bit as well as one or both of the `int1_full` or `int2_full` bits must be set also. The status of the full interrupt may be read back through the `fifo_int` status bit.

Table 12: Interrupt configuration bits relevant for the FIFO controller

Register	Address
<code>h2o_mrk_lvl_trig_ret<6:0></code>	<code>0x3D</code> bits<6:0>
<code>fifo_en</code>	<code>0x15</code> bit 6
<code>fifo_wm_en</code>	<code>0x1E</code> bit 7
<code>int1_fifo</code>	<code>0x18</code> bit 2
<code>int2_fifo</code>	<code>0x18</code> bit 5



6. Register description

6.1 General remarks

The entire communication with the device is performed by reading from and writing to registers. Registers have a width of 8 bits; they are mapped to a common space of 64 addresses from (0x00) up to (0x3F). Within the used range there are several registers which are either completely or partially marked as 'reserved'. Any reserved bit is ignored when it is written and no specific value is guaranteed when read. It is recommended not to use registers at all which are completely marked as 'reserved'. Furthermore it is recommended to mask out (logical *and* with zero) reserved bits of registers which are partially marked as reserved.

Registers with addresses from (0x00) up to (0x0E) are read-only. Any attempt to write to these registers is ignored. There are bits within some registers that trigger internal sequences. These bits are configured for write-only access, e. g. (0x21) *reset_int* or the entire (0x14) *softreset* register, and read as value '0'.

6.2 Register map

Register Address	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0	Access	Reset Value
0x3F	fifo_data[7]	fifo_data[6]	fifo_data[5]	fifo_data[4]	fifo_data[3]	fifo_data[2]	fifo_data[1]	fifo_data[0]	ro	0x00
0x3E	modet[1]	modet[0]							w/r	0x00
0x3D	tag	h2o_mrk_lvl_trig_ret[6]	h2o_mrk_M_trig_ret[5]	h2o_mrk_lvl_trig_ret[4]	h2o_mrk_M_trig_ret[3]	h2o_mrk_lvl_trig_ret[2]	h2o_mrk_M_trig_ret[1]	h2o_mrk_lvl_trig_ret[0]	w/r	0x00
0x3C			rate_ok			bist_fail	bist_rdy	trig_bist	ro	N/A
0x3B	gp0[11]	gp0[10]	gp0[9]	gp0[8]	gp0[7]	gp0[6]	gp0[5]	gp0[4]	w/r	N/A
0x3A	gp0[3]	gp0[2]	gp0[1]	gp0[0]	offset_x[1]	offset_x[0]	offset_y[0]	offset_z[0]	w/r	N/A
0x39	offset_z[11]	offset_z[10]	offset_z[9]	offset_z[8]	offset_z[7]	offset_z[6]	offset_z[5]	offset_z[4]	w/r	N/A
0x38	offset_y[11]	offset_y[10]	offset_y[9]	offset_y[8]	offset_y[7]	offset_y[6]	offset_y[5]	offset_y[4]	w/r	N/A
0x37	offset_x[11]	offset_x[10]	offset_x[9]	offset_x[8]	offset_x[7]	offset_x[6]	offset_x[5]	offset_x[4]	w/r	N/A
0x36	offset_x[3]	offset_x[2]	offset_y[3]	offset_y[2]	offset_y[1]	offset_z[3]	offset_z[2]	offset_z[1]	w/r	N/A
0x35									w/r	0x00
0x34			ext_fifo_s_en	ext_fifo_s_sel	burst_same_en	i2c_wdt_en	i2c_wdt_sel	spi3	w/r	0x00
0x33	rwm_remain[3]	rwm_remain[2]	rwm_remain[1]	rwm_remain[0]	rwm_load	rwm_rdy	rwm_prog_trig	rwm_prog_mode	w/r	0x00
0x32	auto_offset_wordlength[1]	auto_offset_wordlength[0]	fast_offset_wordlength[1]	fast_offset_wordlength[0]	fast_offset_en	fast_offset_en_z	fast_offset_en_y	fast_offset_en_x	w/r	0x00
0x31	slow_offset_th[1]	slow_offset_th[0]	slow_offset_dur[2]	slow_offset_dur[1]	slow_offset_dur[0]	slow_offset_en_z	slow_offset_en_y	slow_offset_en_x	w/r	0x00
0x30									w/r	0xE8
0x2F									w/r	0xE0
0x2E									w/r	0x81
0x2D									w/r	0x40
0x2C									w/r	0x42
0x2B									w/r	0x22
0x2A									w/r	0xE8
0x29									w/r	0x19
0x28									w/r	0x24
0x27	high_dur_z[7]	high_dur_z[6]	high_dur_z[5]	high_dur_z[4]	high_dur_z[3]	high_dur_z[2]	high_dur_z[1]	high_dur_z[0]	w/r	0x19
0x26	high_by_z[1]	high_by_z[0]	high_th_z[4]	high_th_z[3]	high_th_z[2]	high_th_z[1]	high_th_z[0]	high_en_z	w/r	0x02
0x25	high_dur_y[7]	high_dur_y[6]	high_dur_y[5]	high_dur_y[4]	high_dur_y[3]	high_dur_y[2]	high_dur_y[1]	high_dur_y[0]	w/r	0x19
0x24	high_by_y[1]	high_by_y[0]	high_th_y[4]	high_th_y[3]	high_th_y[2]	high_th_y[1]	high_th_y[0]	high_en_y	w/r	0x02
0x23	high_dur_x[7]	high_dur_x[6]	high_dur_x[5]	high_dur_x[4]	high_dur_x[3]	high_dur_x[2]	high_dur_x[1]	high_dur_x[0]	w/r	0x19
0x22	high_by_x[1]	high_by_x[0]	high_th_x[4]	high_th_x[3]	high_th_x[2]	high_th_x[1]	high_th_x[0]	high_en_x	w/r	0x02
0x21	reset_int	offset_reset		latch_status_bits	latch_int[3]	latch_int[2]	latch_int[1]	latch_int[0]	w/r	0x00
0x20									w/r	0x00
0x1F									w/r	0x28
0x1E	fifo_wm_en								w/r	0x08
0x1D									w/r	0xC9
0x1C	awake_dur[1]	awake_dur[0]	any_dursample[1]	any_dursample[0]		any_en_z	any_en_y	any_en_x	w/r	0xA0
0x1B	last_offset_unlilt	any_th[6]	any_th[5]	any_th[4]	any_th[3]	any_th[2]	any_th[1]	any_th[0]	w/r	0x04
0x1A			slow_offset_unlilt		high_unlilt_data		any_unlilt_data		w/r	0x00
0x19					int2_high		int2_any		wo	0x00
0x18	int2_data	int2_fast_offset	int2_fifo	int2_auto_offset	int1_auto_offset	int1_fifo	int1_fast_offset	int1_data	w/r	0x00
0x17					int1_high		int1_any		w/r	0x00
0x16					int2_od	int2_M	int1_od	int1_M	w/r	0x0F
0x15	data_en	fifo_en				auto_offset_en			w/r	0x00
0x14	softreset[7]	softreset[6]	softreset[5]	softreset[4]	softreset[3]	softreset[2]	softreset[1]	softreset[0]	wo	0x00
0x13	data_high_bw	shadow_ds							wo	0x00
0x12	fast_powerup	power_save_mode	ext_trig_sel[1]	ext_trig_sel[0]		autosleep_dur[2]	autosleep_dur[1]	autosleep_dur[0]	w/r	0x00
0x11	suspend		deep_suspend		sleep_dur[2]	sleep_dur[1]	sleep_dur[0]		w/r	0x00
0x10					bw[3]	bw[2]	bw[1]	bw[0]	w/r	0x80
0x0F							range[1]	range[0]	w/r	0x00
0x0E	Overrun	frame_counter[6]	frame_counter[5]	frame_counter[4]	frame_counter[3]	frame_counter[2]	frame_counter[1]	frame_counter[0]	ro	0x00
0x0D									ro	0x00
0x0C					high_sign	high_first_z	high_first_y	high_first_x	ro	0x00
0x0B					any_sign	any_first_z	any_first_y	any_first_x	ro	0x00
0x0A	data_int	auto_offset_int	fast_offset_int	fifo_int					ro	0x00
0x09							any_int		ro	0x00
0x08	temp[7]	temp[6]	temp[5]	temp[4]	temp[3]	temp[2]	temp[1]	temp[0]	ro	0x00
0x07	rate_z[15]	rate_z[14]	rate_z[13]	rate_z[12]	rate_z[11]	rate_z[10]	rate_z[9]	rate_z[8]	ro	0x00
0x06	rate_z[7]	rate_z[6]	rate_z[5]	rate_z[4]	rate_z[3]	rate_z[2]	rate_z[1]	rate_z[0]	ro	0x00
0x05	rate_y[15]	rate_y[14]	rate_y[13]	rate_y[12]	rate_y[11]	rate_y[10]	rate_y[9]	rate_y[8]	ro	0x00
0x04	rate_y[7]	rate_y[6]	rate_y[5]	rate_y[4]	rate_y[3]	rate_y[2]	rate_y[1]	rate_y[0]	ro	0x00
0x03	rate_x[15]	rate_x[14]	rate_x[13]	rate_x[12]	rate_x[11]	rate_x[10]	rate_x[9]	rate_x[8]	ro	0x00
0x02	rate_x[7]	rate_x[6]	rate_x[5]	rate_x[4]	rate_x[3]	rate_x[2]	rate_x[1]	rate_x[0]	ro	0x00
0x01									ro	0x00
0x00	chip_id[7]	chip_id[6]	chip_id[5]	chip_id[4]	chip_id[3]	chip_id[2]	chip_id[1]	chip_id[0]	ro	0x0F
								w/r		
								write only		
								read only		
								ns. future use		

common w/r registers: Application specific settings which are not equal to the default settings, must be re-set to its designated values after POR, soft-reset and wake up from deep suspend.

user w/r registers: Initial default content = 0x00. Freely programmable by the user.

Remains unchanged after POR, soft-reset and wake up from deep suspend.

Figure 8: Register map

Register 0x00 (CHIP_ID)

The register contains the chip identification code.

Name	0x00	CHIP_ID		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	chip_id<7:4>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	chip_id<3:0>			

chip_id<7:0>: Fixed value b'0000'1111 =0x0F

Register 0x01 is reserved

Register 0x02 (RATE_X_LSB)

The register contains the least-significant bits of the X-channel angular rate readout value. When reading out X-channel angular rate values, data consistency is guaranteed if the RATE_X_LSB is read out before the RATE_X_MSB and shadow_dis='0'. In this case, after the RATE_X_LSB has been read, the value in the RATE_X_MSB register is locked until the RATE_X_MSB has been read. This condition is inherently fulfilled if a burst-mode read access is performed. Angular rate data may be read from register RATE_X_LSB at any time except during power-up and in DEEP_SUSPEND mode.

Name	0x02	RATE_X_LSB		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_x_lsb<7:4>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_x_lsb<3:0>			

rate_x_lsb<7:0>: Least significant 8 bits of rate read-back value; (two's-complement format)

Register 0x03 (RATE_X_MSB)

The register contains the most-significant bits of the X-channel angular rate readout value. When reading out X-channel angular rate values, data consistency is guaranteed if the RATE_X_LSB is read out before the RATE_X_MSB and shadow_dis='0'. In this case, after the RATE_X_LSB has been read, the value in the RATE_X_MSB register is locked until the RATE_X_MSB has been read. This condition is inherently fulfilled if a burst-mode read access is performed. Angular rate data may be read from register RATE_X_MSB at any time except during power-up and in DEEP_SUSPEND mode.

Name	0x03	RATE_X_MSB		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_x_msb<15:12>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_x_msb<11:8>			

rate_x_msb<15:8>: Most significant 8 bits of rate read-back value (two's-complement format)

Register 0x04 (RATE_Y_LSB)

The register contains the least-significant bits of the Y-channel angular rate readout value. When reading out Y-channel angular rate values, data consistency is guaranteed if the RATE_Y_LSB is read out before the RATE_Y_MSB and shadow_dis='0'. In this case, after the RATE_Y_LSB has been read, the value in the RATE_Y_MSB register is locked until the RATE_Y_MSB has been read. This condition is inherently fulfilled if a burst-mode read access is performed. Angular rate data may be read from register RATE_Y_LSB at any time except during power-up and in DEEP_SUSPEND mode.

Name	0x04	RATE_Y_LSB		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_y_lsb<7:4>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_y_lsb<3:0>			

rate_y_lsb<7:0>: Least significant 8 bits of rate read-back value; (two's-complement format)

Register 0x05 (RATE_Y_MSB)

The register contains the most-significant bits of the Y-channel angular rate readout value. When reading out Y-channel angular rate values, data consistency is guaranteed if the RATE_Y_LSB is read out before the RATE_Y_MSB and shadow_dis='0'. In this case, after the RATE_Y_LSB has been read, the value in the RATE_Y_MSB register is locked until the RATE_Y_MSB has been read. This condition is inherently fulfilled if a burst-mode read access is performed. Angular rate data may be read from register RATE_Y_MSB at any time except during power-up and in DEEP_SUSPEND mode.

Name	0x05	RATE_Y_MSB		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_y_msb<15:12>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_y_msb<11:8>			

rate_y_msb<15:8>: Most significant 8 bits of rate read-back value (two's-complement format)

Register 0x06 (RATE_Z_LSB)

The register contains the least-significant bits of the Y-channel angular rate readout value. When reading out Y-channel angular rate values, data consistency is guaranteed if the RATE_Z_LSB is read out before the RATE_Z_MSB and shadow_dis='0'. In this case, after the RATE_Z_LSB has been read, the value in the RATE_Z_MSB register is locked until the RATE_Z_MSB has been read. This condition is inherently fulfilled if a burst-mode read access is performed. Angular rate data may be read from register RATE_Y_LSB at any time except during power-up and in DEEP_SUSPEND mode.

Name	0x06	RATE_Z_LSB		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_z_lsb<7:4>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_z_lsb<3:0>			

rate_z_lsb<7:0>: Least significant 8 bits of rate read-back value; (two's-complement format)

Register 0x07 (RATE_Z_MSB)

The register contains the most-significant bits of the Y-channel angular rate readout value. When reading out Y-channel angular rate values, data consistency is guaranteed if the RATE_Z_LSB is read out before the RATE_Z_MSB and shadow_dis='0'. In this case, after the RATE_Z_LSB has been read, the value in the RATE_Z_MSB register is locked until the RATE_Z_MSB has been read. This condition is inherently fulfilled if a burst-mode read access is performed. Angular rate data may be read from register RATE_Z_MSB at any time except during power-up and in DEEP_SUSPEND mode.

Name	0x07	RATE_Z_MSB		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_z_msb<15:12>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	rate_z_msb<11:8>			

rate_z_msb<15:8>: Most significant 8 bits of rate read-back value (two's-complement format)

**Register 0x08 (TEMP)**

The register contains the current chip temperature represented in two's complement format. A readout value of temp<7:0>=0x00 corresponds to a temperature of 23°C.

Name	0x08	TEMP		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	0	0	0	0
Content	temp<7:4>			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	0	0	0	0
Content	temp<3:0>			

temp<7:0>: Temperature value (two's complement format)

Register 0x09 (INT_STATUS_0)

The register contains interrupt status bits.

Name	0x09	INT_STATUS_0		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	reserved			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	reserved	any_int	high_int	reserved

any_int: Any motion interrupt status

high_int: High rate interrupt status

Register 0x0A (INT_STATUS_1)

The register contains interrupt status bits.

Name	0x0A	INT_STATUS_1		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	data_int	auto_offset_int	fast_offset_int	fifo_int

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	reserved			

data_int: New data interrupt status

auto_offset_int: Auto Offset interrupt status

fast_offset_int: Fast Offset interrupt status

fifo_int: Fifo interrupt status

Register 0x0B (INT_STATUS_2)

The register contains any motion interrupt status bits,

Name	0x0B	INT_STATUS_2		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	reserved			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	any_sign	any_first_z	any_first_y	any_first_x

any_sign: sign of any motion interrupt ('1'= positive, '0'=negative)
 any_first_z: '1' indicates that z-axis is triggering axis of any motion interrupt
 any_first_y: '1' indicates that y-axis is triggering axis of any motion interrupt
 any_first_x: '1' indicates that z-axis is triggering axis of any motion interrupt

Register 0x0C (INT_STATUS_3)

The register contains high rate interrupt status bits,

Name	0x0C	INT_STATUS_3		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	reserved			

Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	high_sign	high_first_z	high_first_y	high_first_x

high_sign: sign of high rate interrupt ('1'= positive, '0'=negative)
 high_first_z: '1' indicates that z-axis is triggering axis of high rate interrupt
 high_first_y: '1' indicates that y-axis is triggering axis of high rate interrupt
 high_first_x: '1' indicates that z-axis is triggering axis of high rate interrupt



Register 0x0D is reserved

Register 0x0E (FIFO_STATUS)

The register contains FIFO status flags.

Name	0x0E	FIFO_STATUS		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	fifo_overrun	fifo_frame_counter<6:4>		
Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	fifo_frame_counter<3:0>			

fifo_overrun: FIFO overrun condition has '1' → occurred, or '0' → not occurred; flag can be cleared by writing to the FIFO configuration register FIFO_CONFIG_1 only

fifo_frame_counter<6:0>:

Current fill level of FIFO buffer. An empty FIFO corresponds to 0x00. The frame counter can be cleared by reading out all frames from the FIFO buffer or writing to the FIFO configuration register FIFO_CONFIG_1.

**Register 0x0F (RANGE)**

The BMG160 supports four different angular rate measurement ranges. A measurement range is selected by setting the (0x0F) range bits as follows:

Name	0x0F	RANGE		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	fixed<1:0>	reserved		

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved	range<2:0>		

range<2:0>: Angular Rate Range and Resolution.

range<2:0>	Full Scale	Resolution
'000'	±2000°/s	16.4 LSB/°/s ⇔ 61.0 m°/s / LSB
'001'	±1000°/s	32.8 LSB/°/s ⇔ 30.5 m°/s / LSB
'010'	±500°/s	65.6 LSB/°/s ⇔ 15.3 m°/s / LSB
'011'	±250°/s	131.2 LSB/°/s ⇔ 7.6 m°/s / LSB
'100'	±125°/s	262.4 LSB/°/s ⇔ 3.8m°/s / LSB
'101', '110', '111'	reserved	

fixed<1:0>: write '10'

reserved: write '0'

**Register 0x10 (BW)**

The register allows the selection of the rate data filter bandwidth.

Name	0x10	BW		
Bit	7	6	5	4
Read/Write	R	R/W	R/W	R/W
Reset Value	1	0	0	0
Content	reserved			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	bw<3:0>			

bw<3:0>:

0x10 bits<3:0>	Decimation Factor	ODR	Filter Bandwidth
'0111'	20	100 Hz	32 Hz
'0110'	10	200 Hz	64 Hz
'0101'	20	100 Hz	12 Hz
'0100'	10	200 Hz	23 Hz
'0011'	5	400 Hz	47 Hz
'0010'	2	1000 Hz	116 Hz
'0001'	0	2000 Hz	230 Hz
'0000'	0	2000 Hz	Unfiltered (523Hz)
'1xxx'	Unused / Reserved	Unused / Reserved	Unused / Reserved

reserved: write '0'

Register 0x11 (LPM1)

Selection of the main power modes.

Name	0x11	LPM1		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	suspend	reserved	deep_suspend	reserved

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	sleep_dur[2]	sleep_dur[1]	sleep_dur[0]	reserved

suspend, deep_suspend:

Main power mode configuration setting {suspend; deep_suspend}:

 {0; 0} → NORMAL mode;
 {0; 1} → DEEP_SUSPEND mode;
 {1; 0} → SUSPEND mode;
 {all other} → illegal

Please note that only certain power mode transitions are permitted.

Please note, that all application specific settings which are not equal to the default settings (refer to 6.2 register map), must be re-set to its designated values after DEEP_SUSPEND.

sleep_dur<0:2>: time in ms in fast-power-up mode under advanced power-saving mode.

sleep_dur<2:0>	Time (ms)
'000'	2 ms
'001'	4 ms
'010'	5 ms
'011'	8 ms
'100'	10 ms
'101'	15 ms
'110'	18 ms
'111'	20 ms

reserved: write '0'

Register 0x12 (LPM2)

Configuration settings for fast power-up and external trigger.

Name	0x12	LPM2		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	fast_powerup	power_save_mode	ext_trig_sel[1]	ext_trig_sel[0]

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved	autosleep_dur[2]	autosleep_dur[1]	autosleep_dur[0]

fast powerup: 1 → Drive stays active for suspend mode in order to have a short wake-up time.

0 → Drive is switched off for suspend mode

ext_trig_sel:

ext_trig_sel<1:0>	Trigger source
'00'	No
'01'	INT1 pin
'10'	INT2 pin
'11'	SDO pin (SPI3 mode)

Autosleep<0:2>: time in ms in normal mode under advanced power-saving mode.

autosleep_dur<2:0>	Time (ms)
'000'	Not allowed
'001'	4 ms
'010'	5 ms
'011'	8 ms
'100'	10 ms
'101'	15 ms
'110'	20 ms
'111'	40 ms

reserved: write '0'

Register 0x13 (RATE_HBW)

Angular rate data acquisition and data output format.

Name	0x13	RATE_HBW		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0 (1 in 8-bit mode)	0	0
Content	data_high_bw	shadow_dis	reserved	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved			

data_high_bw: select whether '1' → unfiltered, or '0' → filtered data may be read from the rate data registers.

shadow_dis: '1' → disable, or '0' → the shadowing mechanism for the rate data output registers. When shadowing is enabled, the content of the rate data component in the MSB register is locked, when the component in the LSB is read, thereby ensuring the integrity of the rate data during read-out. The lock is removed when the MSB is read.

reserved: write '0'

Register 0x14 (BGW_SOFTRESET)

Controls user triggered reset of the sensor.

Name	0x14	BGW_SOFTRESET		
Bit	7	6	5	4
Read/Write	W	W	W	W
Reset Value	0	0	0	0
Content	softreset			

Bit	3	2	1	0
Read/Write	W	W	W	W
Reset Value	0	0	0	0
Content	softreset			

softreset: 0xB6 → trigger a reset. Other values are ignored. Following a delay, all user configuration settings are overwritten with their default state or the setting stored in the NVM, wherever applicable. This register is functional in all operation modes. Please note, that all application specific settings which are not equal to the default settings (refer to 6.2 register map), must be re-set to its designated values.

Register 0x15 (INT_EN_0)

Controls which interrupts are enabled.

Name	0x15	INT_EN_0		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	data_en	fifo_en	reserved	
Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved		auto_offset_en	reserved

data_en: '1' ('0') enables (disables) new data interrupt

fifo_en: '1' ('0') enables (disables) fifo interrupt

auto_offset_en: '1' ('0') enables (disables) auto-offset compensation

reserved: write '0'

Register 0x16 (INT_EN_1)

Contains interrupt pin configurations.

Name	0x16	INT_EN_1		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved			
Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	1	1	1
Content	int2_od	int2_lvl	int1_od	int1_lvl

int2_od: '0' ('1') selects push-pull, '1' selects open drive for INT2

int2_lvl: '0' ('1') selects active level '0' ('1') for INT2

int1_od: '0' ('1') selects push-pull, '1' selects open drive for INT1

int1_lvl: '0' ('1') selects active level '0' ('1') for INT1

reserved: write '0'

Register 0x17 (INT_MAP_0)

Controls which interrupt signals are mapped to the INT1 pin.

Name	0x17	INT_MAP_0		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved			
Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	int1_high	reserved	int1_any	reserved

int1_high: map high rate interrupt to INT1 pin: '0'→disabled, or '1' →enabled
 int1_any: map Any-Motion to INT1 pin: '0'→disabled, or '1' →enabled
 reserved: write '0'

Register 0x18 (INT_MAP_1)

Controls which interrupt signals are mapped to the INT1 pin and INT2 pin.

Name	0x1B	INT_MAP_1		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	int2_data	int2_fast_offset	int2_fifo	int2_auto_offset
Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	int1_auto_offset	int1_fifo	int1_fast_offset	int1_data

int2_data: map new data interrupt to INT2 pin: '0'→disabled, or '1' →enabled
 int2_fast_offset: map FastOffset interrupt to INT2 pin: '0'→disabled, or '1' →enabled
 int2_fifo: map Fifo interrupt to INT2 pin: '0'→disabled, or '1' →enabled
 int2_auto_offset: map AutoOffset tap interrupt to INT2 pin: '0'→disabled, or '1' →enabled
 int1_auto_offset: map AutoOffset tap interrupt to INT1 pin: '0'→disabled, or '1' →enabled
 int1_fifo: map Fifo interrupt to INT1 pin: '0'→disabled, or '1' →enabled
 int1_fast_offset: map FastOffset interrupt to INT1 pin: '0'→disabled, or '1' →enabled
 int1_data: map new data interrupt to INT1 pin: '0'→disabled, or '1' →enabled

Register 0x19 (INT_MAP_2)

Controls which interrupt signals are mapped to the INT2 pin.

Name	0x19	INT_MAP_2		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	Int2_high	reserved	Int2_any	reserved

Int2_high: map high rate interrupt to INT2 pin: '0'→disabled, or '1' →enabled

Int2_any: map Any-Motion to INT2 pin: '0'→disabled, or '1' →enabled

reserved: write '0'

Register 0x1A

Contains the data source definition of those interrupts with selectable data source.

Name	0x1A			
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved		slow_offset_unfilt	reserved

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	high_unfilt_data	reserved	any_unfilt_data	reserved

slow_offset_unfilt: '1' ('0') selects unfiltered (filtered) data for slow offset compensation

high_unfilt_data: '1' ('0') selects unfiltered (filtered) data for high rate interrupt

any_unfilt_data: '1' ('0') selects unfiltered (filtered) data for any motion interrupt

reserved: write '0'

Register 0x1B

Contains the data source definition of fast offset compensation and the any motion threshold.

Name	0x1B			
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	fast_offset_unfilt	any_th <6:4>		

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	1	0	0
Content	any_th <3:0>			

fast_offset_unfilt: '1' ('0') selects unfiltered (filtered) data for fast offset compensation

any_th: any_th = (1 + any_th(register value)) * 16 LSB

The any_th scales with the range setting

Register 0x1C

Name	0x1C			
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	0	1	0
Content	awake_dur <1:0>		any_dursample <1:0>	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved	any_en_z	any_en_y	any_en_x

awake_dur: 0=8 samples, 1=16 samples, 2=32 samples, 3=64 samples

any_dursample: 0=4 samples, 1=8 samples, 2=12 samples, 3=16 samples

any_en_z: '1' ('0') enables (disables) any motion interrupt for z-axis

any_en_y: '1' ('0') enables (disables) any motion interrupt for y-axis

any_en_x: '1' ('0') enables (disables) any motion interrupt for z-axis

If one of the bits any_x/y/z is enabled, the any motion interrupt is enabled

reserved: write '0'



Register 0x1D is reserved.

Register 0x1E

Name	0x1E			
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	0	0	0
Content	fifo_wm_en	reserved		

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	0	0	0
Content	reserved			

fifo_wm_en: '1' ('0') enables (disables) fifo water mark level interrupt

reserved: write '0'

Registers 0x1F to 0x20 are reserved

**Register 0x21 (INT_RST_LATCH)**

Contains the interrupt reset bit and the interrupt mode selection.

Name	0x21	INT_RST_LATCH		
Bit	7	6	5	4
Read/Write	W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reset_int	offset_reset	reserved	latch_status_bit
Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	latch_int<3:0>			

reset_int: write '1' → clear any latched interrupts, or '0' → keep latched interrupts active

offset_reset: write '1' → resets internal interrupt status of each interrupt
write '1' → resets the Offset value calculated with FastOffset, SlowOffset & AutoOffset

latch_int<3:0>: '0000b' → non-latched, '0001b' → temporary, 250 ms,
'0010b' → temporary, 500 ms, '0011b' → temporary, 1 s,
'0100b' → temporary, 2 s, '0101b' → temporary, 4 s,
'0110b' → temporary, 8 s, '0111b' → latched,
'1000b' → non-latched, '1001b' → temporary, 250 μs,
'1010b' → temporary, 500 μs, '1011b' → temporary, 1 ms,
'1100b' → temporary, 12.5 ms, '1101b' → temporary, 25 ms,
'1110b' → temporary, 50 ms, '1111b' → latched

reserved: write '0'

**Register 0x22 (High_Th_x)**

Contains the high rate threshold and high rate hysteresis setting for the x-axis

Name	0x22	High_Th_x		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	high_hy_x <1:0>		high_th_x <4:3>	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	1	0
Content	high_th_x <2:0>			high_en_x

high_hy_x: $high_hy_x = (255 + 256 * high_hy_x(\text{register value})) * 4 \text{ LSB}$

The high_hy_x scales with the range setting

high_th_x: $high_th_x = (255 + 256 * high_th_x(\text{register value})) * 4 \text{ LSB}$

The high_th_x scales with the range setting

high_en_x: '1' ('0') enables (disables) high rate interrupt for x-axis

Register 0x23 (High_Dur_x)

Contains high rate duration setting for the x-axis.

Name	0x23	High_Dur_x		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	1
Content	high_dur_x <7:4>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	0	0	1
Content	high_dur_x <3:0>			

$$\text{high_dur_x: } \quad \text{high_dur time_x} = (1 + \text{high_dur_x}(\text{register value})) * 2.5\text{ms}$$
Register 0x24 (High_Th_y)

Contains the high rate threshold and high rate hysteresis setting for the y-axis

Name	0x24	High_Th_y		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	high_hy_y <1:0>		high_th_y <4:3>	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	1	0
Content	high_th_y <2:0>			high_en_y

$$\text{high_hy_y: } \quad \text{high_hy_y} = (255 + 256 * \text{high_hy_y}(\text{register value})) * 4 \text{ LSB}$$

The high_hy_y scales with the range setting

$$\text{high_th_y} \quad \text{high_th_x} = (255 + 256 * \text{high_th_y}(\text{register value})) * 4 \text{ LSB}$$

The high_th_y scales with the range setting

$$\text{high_en_y} \quad \text{'1' ('0')} \text{ enables (disables) high rate interrupt for y-axis}$$

Register 0x25 (High_Dur_y)

Contains high rate duration setting for the x-axis.

Name	0x25	High_Dur_y		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	1
Content	high_dur_y <7:4>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	0	0	1
Content	high_dur_y <3:0>			

$$\text{high_dur_y:} \quad \text{high_dur time_y} = (1 + \text{high_dur_y}(\text{register value})) * 2.5\text{ms}$$
Register 0x26 (High_Th_z)

Contains the high rate threshold and high rate hysteresis setting for the z-axis

Name	0x26	High_Th_z		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	high_hy_z <1:0>		high_th_z <4:3>	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	1	0
Content	high_th_z <2:0>			high_en_z

$$\text{high_hy_z:} \quad \text{high_hy_z} = (255 + 256 * \text{high_hx_z}(\text{register value})) * 4 \text{ LSB}$$

The high_hy_x scales with the range setting

$$\text{high_th_z} \quad \text{high_th_z} = (255 + 256 * \text{high_th_z}(\text{register value})) * 4 \text{ LSB}$$

The high_th_z scales with the range setting

$$\text{high_en_z} \quad \text{'1' ('0')} \text{ enables (disables) high rate interrupt for z-axis}$$

Register 0x27 (High_Dur_z)

Contains high rate duration setting for the z-axis.

Name	0x27	High_dur_z		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	1
Content	high_dur_z <7:4>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	0	0	1
Content	high_dur_z <3:0>			

$$\text{high_dur_z: } \quad \text{high_dur time_z} = (1 + \text{high_dur_z}(\text{register value})) * 2.5\text{ms}$$
Registers 0x28 to 0x30 are reserved
Register 0x31 (SOC)

Contains the slow offset cancellation setting.

Name	0x31	SOC		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	1	1	0
Content	Slow_offset_th<1:0>		Slow_offset_dur<2:1>	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	Slow_offset_dur <0>	slow_offset_en_z	slow_offset_en_y	slow_offset_en_x

Slow_offset_th: 0=0.1°/s, 1=0.2°/s, 2=0.5°/s, 3=1°/s

 Slow_offset_dur: 0=40ms, 1=80ms, 2=160ms, 3=320ms, 4=640ms, 5=1280ms,
 6 and 7=unused

slow_offset_en_z: '1' ('0') enables (disables) slow offset compensation for z-axis

slow_offset_en_y: '1' ('0') enables (disables) slow offset compensation for y-axis

slow_offset_en_x: '1' ('0') enables (disables) slow offset compensation for x-axis

**Register 0x32 (A_FOC)**

Contains the fast offset cancellation setting.

Name	0x32	A_FOC		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	1	1	0	0
Content	auto_offset_wordlength<1:0>		fast_offset_wordlength<1:0>	

Bit	3	2	1	0
Read/Write	R	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	fast_offset_en	fast_offset_en_z	fast_offset_en_y	fast_offset_en_x

auto_offset_wordlength: 0=32 samples, 1=64 samples, 2=128 samples, 3=256 samples

fast_offset_wordlength: 0=32 samples, 1=64 samples, 2=128 samples, 3=256 samples

fast_offset_en: write '1' → triggers the fast offset compensation for the enabled axes

fast_offset_en_z: '1' ('0') enables (disables) fast offset compensation for z-axis

fast_offset_en_y: '1' ('0') enables (disables) fast offset compensation for y-axis

fast_offset_en_x: '1' ('0') enables (disables) fast offset compensation for x-axis

Register 0x33 (TRIM_NVM_CTRL)

Contains the control settings for the few-time programmable non-volatile memory (NVM).

Name	0x33	TRIM_NVM_CTRL		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	nvm_remain<3:0>			

Bit	3	2	1	0
Read/Write	R/W	R	W	R/W
Reset Value	0	n/a	0	0
Content	nvm_load	nvm_rdy	nvm_prog_trig	nvm_prog_mode

nvm_remain<3:0>: number of remaining write cycles permitted for NVM; the number is decremented each time a write to the NVM is triggered

nvm_load: '1' → trigger, or '0' → do not trigger an update of all configuration registers from NVM; the nvm_rdy flag must be '1' prior to triggering the update

nvm_rdy: status of NVM controller: '0' → NVM write / NVM update operation is in progress, '1' → NVM is ready to accept a new write or update trigger

nvm_prog_trig: '1' → trigger, or '0' → do not trigger an NVM write operation; the trigger is only accepted if the NVM was unlocked before and nvm_remain<3:0> is greater than '0'; flag nvm_rdy must be '1' prior to triggering the write cycle

nvm_prog_mode: '1' → unlock, or '0' → lock NVM write operation

Register 0x34 (BGW_SPI3_WDT)

Contains settings for the digital interfaces.

Name	0x34	BGW_SPI3_WDT		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	Reserved			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved	i2c_wdt_en	i2c_wdt_sel	spi3

reserved: write '0'

ext_fifo_s_en: enables external FIFO synchronization mode, '1' → enable, '0' → disable

ext_fifo_s_sel: selects source for external FIFO synchronization
'1' → source = INT2
'0' → source = INT1i2c_wdt_en: if I²C interface mode is selected then '1' → enable, or '0' → disables the watchdog at the SDI pin (= SDA for I²C)i2c_wdt_sel: select an I²C watchdog timer period of '0' → 1 ms, or '1' → 50 ms

spi3: select '0' → 4-wire SPI, or '1' → 3-wire SPI mode

Register 0x35 is reserved

**Register 0x36 (OFC1)**

Contains offset compensation values.

Name	0x36	OFC1		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_x<3:2>		offset_y<3:2>	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_y<1>	offset_z<3:1>		

offset_x<3:2>: setting of offset calibration values X-channel

offset_y<3:1>: setting of offset calibration values Y-channel

offset_z<3:1>: setting of offset calibration values Z-channel

**Register 0x37 (OFC2)**

Contains offset compensation values for X-channel.

Name	0x37	OFC2		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_x<11:8>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_x<7:4>			

offset_x <11:4>: offset value, which is subtracted from the internal filtered and unfiltered x-axis data; please refer to the following table for the scaling of the offset register; the content of the offset_x<11:4> may be written to the NVM; it is automatically restored from the NVM after each power-on or softreset; offset_x<11:4> may be written directly by the user.

Example:

Original readout value	Value in offset register	Compensated readout value
0 °/s	2047	-124.94 °/s
0 °/s	0	0 g
0 °/s	-2048	125 °/s

**Register 0x38 (OFC3)**

Contains offset compensation values for Y-channel.

Name	0x38	OFC3		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_y<11:8>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_y<7:4>			

offset_y <11:4>: offset value, which is subtracted from the internal filtered and unfiltered y-axis data; please refer to the following table for the scaling of the offset register; the content of the offset_y<11:4> may be written to the NVM; it is automatically restored from the NVM after each power-on or softreset; offset_y<11:4> may be written directly by the user.

For reference see example at GYR Register 0x37 (OFC2)

Register 0x39 (OFC4)

Contains offset compensation values for Z-channel.

Name	0x39	OFC4		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_z<11:8>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_z<7:4>			

offset_z <11:4>: offset value, which is subtracted from the internal filtered and unfiltered z-axis data; please refer to the following table for the scaling of the offset register; the content of the offset_z<11:4> may be written to the NVM; it is automatically restored from the NVM after each power-on or softreset; offset_z<11:4> may be written directly by the user.

For reference see example at GYR Register 0x37 (OFC2)

Register 0x3A (TRIM_GP0)

Contains general purpose data register with NVM back-up.

Name	0x3A	TRIM_GP0		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	X	X	X	X
Content	GP0<3:0>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	offset_x<1:0>		offset_y<0>	offset_z<0>

GP0<3:0>: general purpose NVM image register not linked to any sensor-specific functionality; register may be written to NVM and is restored after each power-up or software reset

offset_x<1:0>: setting of offset calibration values X-channel

offset_y<0>: setting of offset calibration values Y-channel

offset_z<0>: setting of offset calibration values Z-channel

Register 0x3B (TRIM_GP1)

Contains general purpose data register with NVM back-up.

Name	0x3B	TRIM_GP1		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	X	X	X	X
Content	GP1<7:4>			

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	X	X	X	X
Content	GP1<3:0>			

GP1<7:0>: general purpose NVM image register not linked to any sensor-specific functionality; register may be written to NVM and is restored after each power-up or software reset

Register 0x3C (BIST)

Contains Built in Self-Test (BIST) possibilities:

Name	0x3C	BIST		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	reserved	reserved	reserved	rate_ok

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R
Reset Value	0	0	0	0
Content	reserved	bist_fail	bist_rdy	trig_bist

Rate ok: '1' indicates proper sensor function, no trigger is needed for this

Trig_bist: write '1' in order to perform the bist test

Bist_rdy: if bist_rdy is '1' and bist_fail is '0' result of bist test is ok means "sensor ok"
 If bist_rdy is '1' and bist_fail is '1' result of bist test is not ok means "sensor values not in expected range"

**Register 0x3D (FIFO_CONFIG_0)**

Contains the FIFO watermark level.

Name	0x3D	FIFO_CONFIG_0		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	n/a	n/a	0	0
Content	tag	fifo_water_mark_level_trigger_retain<6:4>		

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	fifo_water_mark_level_trigger_retain<3:0>			

tag: '1' ('0') enables (disables) fifo tag (interrupt)

Address: 0x3D bit 7	tag	Interrupt data stored in FIFO
'0' (Default)		Do not collect Interrupts
'1'		collect Interrupts

fifo_water_mark_level_trigger_retain<6:0>:

fifo_water_mark_level_trigger_retain<6:0> defines the FIFO watermark level. An interrupt will be generated, when the number of entries in the FIFO exceeds fifo_water_mark_level_trigger_retain<6:0>;

**Register 0x3E (FIFO_CONFIG_1)**

Contains FIFO configuration settings. The FIFO buffer memory is cleared and the fifo-full flag is cleared when writing to FIFO_CONFIG_1 register.

Name	0x3E	FIFO_CONFIG_1		
Bit	7	6	5	4
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	fifo_mode<1:0>		Reserved	

Bit	3	2	1	0
Read/Write	R/W	R/W	R/W	R/W
Reset Value	0	0	0	0
Content	Reserved		fifo_data_select<1:0>	

fifo_mode<1:0>: selects the FIFO operating mode:
 '00b' → BYPASS (buffer depth of 1 frame; old data is discarded),
 '01b' → FIFO (data collection stops when buffer is filled with 32 frames),
 '10b' → STREAM (sampling continues when buffer is full; old is discarded),
 '11b' → reserved, do not use

fifo_data_select<1:0>:

Address: 0x3E bits<1:0> data_select	data of axis stored in FIFO
'00' (Default)	X,Y,Z
'01'	X only
'10'	Y only
'11'	Z only

reserved: write '0'

Register 0x3F (FIFO_DATA)

FIFO data readout register. The format of the LSB and MSB components corresponds to that of the angular rate data readout registers.. Read burst access may be used since the address counter will not increment when the read burst is started at the address of FIFO_DATA. The entire frame is discarded when a frame is only partially read out.

Name	0x3F	FIFO_DATA		
Bit	7	6	5	4
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	fifo_data_output_register<7:4>			
Bit	3	2	1	0
Read/Write	R	R	R	R
Reset Value	n/a	n/a	n/a	n/a
Content	fifo_data_output_register<3:0>			

fifo_data_output_register<7:0>:

FIFO data readout; data format depends on the setting of register fifo_data_select<1:0>:

if X+Y+Z data are selected, the data of frame n is reading out in the order of X-lsb(n), X-msb(n), Y-lsb(n), Y-msb(n), Z-lsb(n), Z-msb(n);
 if X-only is selected, the data of frame n and n+1 are reading out in the order of X-lsb(n), X-msb(n), X-lsb(n+1), X-msb(n+1); the Y-only and Z-only modes behave analogously

7. Digital interfaces

The BMG160 can connect to the host system via three interfaces:

- SPI (3-wire, 4-wire)
- I²C
- Two interrupt pins / SDO Pin

The BMG160 is able to operate in two serial interface modes:

- SPI mode: SPI3-wire and SPI4-wire can be used with different clock polarity modes (SPI mode0 and SPI mode3). The clock polarity is detected automatically by the BMG160.
- I²C mode: Both standard and fast modes are supported.

The active interface is selected through the PS-pin (see below).

Table 13: Interface Mode Selection

Mode	PS-Pin	spi3 (0x34 bit 0)
SPI 4-wire (default)	0	0
SPI 3-wire	0	1
I ² C	1	X

Please note that the PS pin must be connected to the appropriate supply during power-up. Switching from I²C mode to SPI mode and vice versa during operation is not permitted. Switching between SPI3 and SPI4 is permitted during normal operation.

Both interfaces share the same pins. The mapping for each interface is given in the following table:

Table 14: Mapping of the interface pins

Pin#	Name	use w/ SPI	use w/ I ² C	Description
8	SDO	SDO	address	SPI: Data Output (4-wire mode) I ² C: Used to set LSB of I ² C address
9	SDx	SDI	SDA	SPI: Data Input (4-wire mode) Data Input/ Output (3-wire mode) I ² C: Serial Data
5	CSB	CSB	unused	Chip Select (enable)
7	SCx	SCK	SCL	SPI: Serial Clock I ² C: Serial Clock

The following table shows the electrical specifications of the interface pins:

Table 15: Electrical specification of the interface pins

Parameter	Symbol	Condition	Min	Typ	Max	Units
Pull-up Resistance, CSB pin	R_{up}	Internal Pull-up Resistance to VDDIO	75	100	125	k Ω
Input Capacitance	C_{in}			5	10	pF
I ² C Bus Load Capacitance (max. drive capability)	C_{I2C_Load}				400	pF

7.1 Serial peripheral interface (SPI)

The timing specification for SPI of the BMG160 is given in the following table:

Table 16: SPI timing

Parameter	Symbol	Condition	Min	Max	Units
Clock Frequency	f_{SPI}	Max. Load on SDI or SDO = 25pF, $V_{DDIO} \geq 1.62V$		10	MHz
		$V_{DDIO} < 1.62V$		7.5	MHz
SCK Low Pulse	t_{SCKL}		20		ns
SCK High Pulse	t_{SCKH}		20		ns
SDI Setup Time	t_{SDI_setup}		20		ns
SDI Hold Time	t_{SDI_hold}		20		ns
SDO Output Delay	t_{SDO_OD}	Load = 25pF, $V_{DDIO} \geq 1.62V$		30	ns
		Load = 25pF, $V_{DDIO} < 1.62V$		50	ns
		Load = 250pF, $V_{DDIO} > 2.4V$		40	ns
CSB Setup Time	t_{CSB_setup}		20		ns
CSB Hold Time	t_{CSB_hold}		40		ns
Idle time between write accesses, normal mode, standby mode, low-power mode 2	$t_{IDLE_wacc_nm}$		2		μs
Idle time between write accesses, suspend mode, low-power mode 1	$t_{IDLE_wacc_sum}$		450		μs

The following figure shows the definition of the SPI timings given in the following figure:

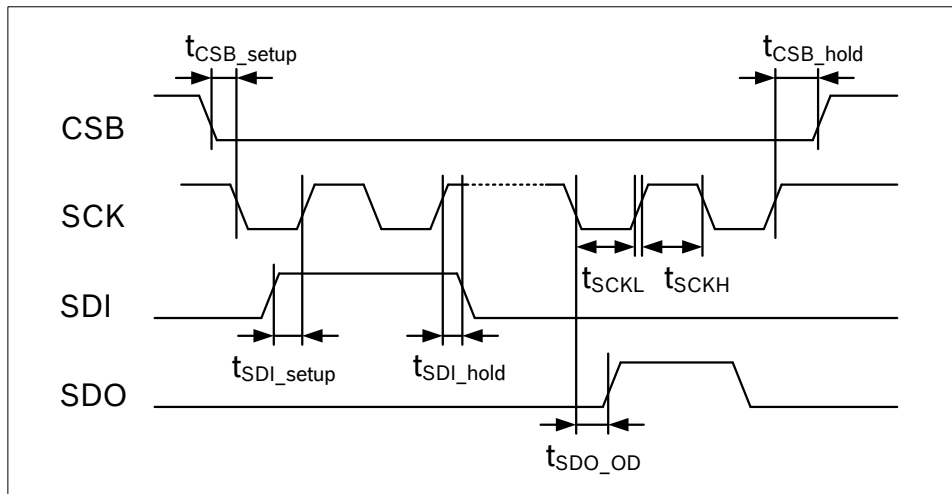


Figure 9: SPI timing diagram

The SPI interface of the BMG160 is compatible with two modes, '00' and '11'. The automatic selection between [CPOL = '0' and CPHA = '0'] and [CPOL = '1' and CPHA = '1'] is controlled based on the value of SCK after a falling edge of CSB.

Two configurations of the SPI interface are supported by the BMG160: 4-wire and 3-wire. The same protocol is used by both configurations. The device operates in 4-wire configuration by default. It can be switched to 3-wire configuration by writing '1' to (0x34) spi3. Pin SDI is used as the common data pin in 3-wire configuration.

For single byte read as well as write operations, 16-bit protocols are used. The BMG160 also supports multiple-byte read operations.

In SPI 4-wire configuration CSB (chip select low active), SCK (serial clock), SDI (serial data input), and SDO (serial data output) pins are used. The communication starts when the CSB is pulled low by the SPI master and stops when CSB is pulled high. SCK is also controlled by SPI master. SDI and SDO are driven at the falling edge of SCK and should be captured at the rising edge of SCK.

The basic write operation waveform for 4-wire configuration is depicted in Figure 10. During the entire write cycle SDO remains in high-impedance state.

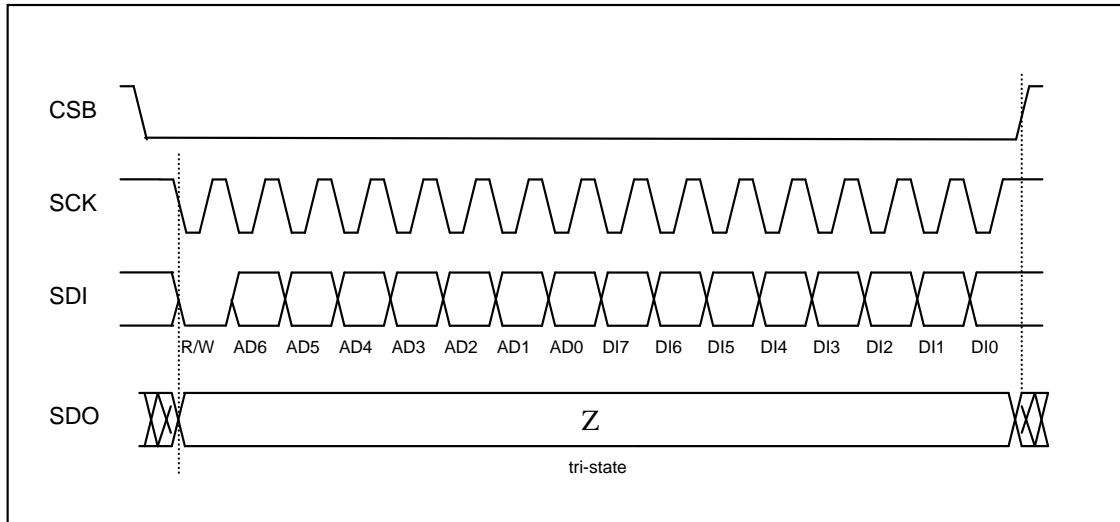


Figure 10: 4-wire basic SPI write sequence (mode '11')

The basic read operation waveform for 4-wire configuration is depicted in Figure 11:

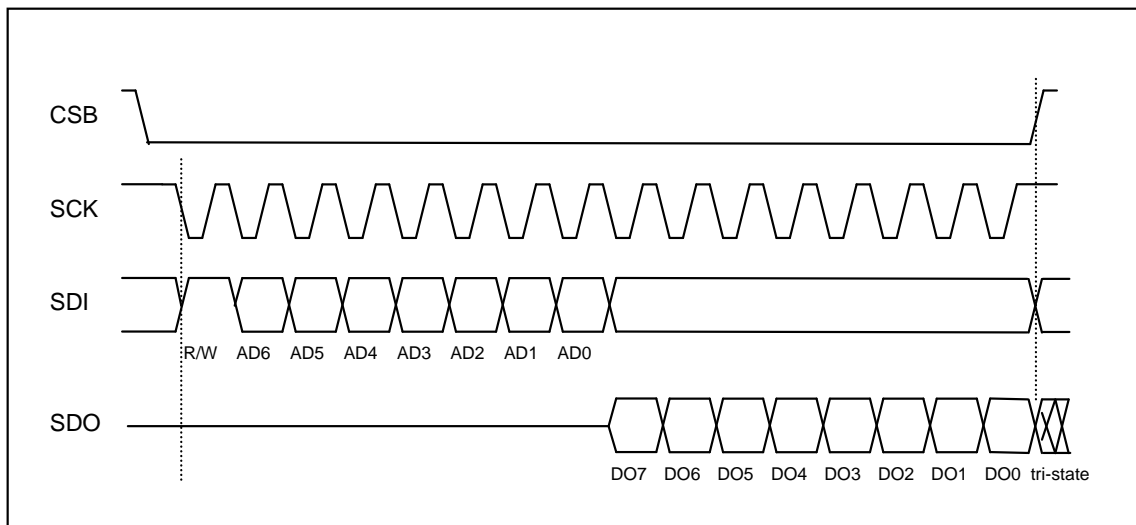


Figure 11: 4-wire basic SPI read sequence (mode '11')

The data bits are used as follows:

Bit0: Read/Write bit. When 0, the data SDI is written into the chip. When 1, the data SDO from the chip is read.

Bit1-7: Address AD(6:0).

Bit8-15: when in write mode, these are the data SDI, which will be written into the address. When in read mode, these are the data SDO, which are read from the address.

Multiple read operations are possible by keeping CSB low and continuing the data transfer. Only the first register address has to be written. Addresses are automatically incremented after each read access as long as CSB stays active low.

The principle of multiple read is shown in Figure 12:

		Control byte							Data byte							Data byte							Data byte												
Start	RW	Register address (02h)							Data register - adress 02h							Data register - adress 03h							Data register - adress 04h							Stop					
CSB = 0	1	0	0	0	0	0	1	0	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	X	CSB = 1

Figure 12: SPI multiple read

In SPI 3-wire configuration CSB (chip select low active), SCK (serial clock), and SDI (serial data input and output) pins are used. The communication starts when the CSB is pulled low by the SPI master and stops when CSB is pulled high. SCK is also controlled by SPI master. SDI is driven (when used as input of the device) at the falling edge of SCK and should be captured (when used as the output of the device) at the rising edge of SCK.

The protocol as such is the same in 3-wire configuration as it is in 4-wire configuration. The basic operation waveform (read or write access) for 3-wire configuration is depicted in Figure 13:

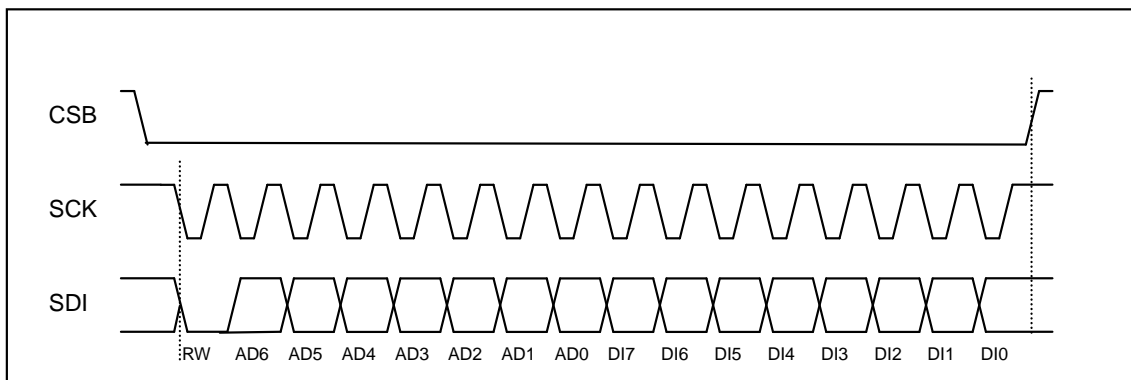


Figure 13: 3-wire basic SPI read or write sequence (mode '11')

7.2 Inter-Integrated Circuit (I²C)

The I²C bus uses SCL (= SCx pin, serial clock) and SDA (= SDx pin, serial data input and output) signal lines. Both lines are connected to V_{DDIO} externally via pull-up resistors so that they are pulled high when the bus is free.

The I²C interface of the BMG160 is compatible with the I²C Specification UM10204 Rev. 03 (19 June 2007), available at <http://www.nxp.com>. The BMG160 supports I²C standard mode and fast mode, only 7-bit address mode is supported. For V_{DDIO} = 1.2V to 1.8V the guaranteed voltage output levels are slightly relaxed as described in the Parameter Specification (Table 1).

The default I²C address of the device is 1101000b (0x68). It is used if the SDO pin is pulled to 'GND'. The alternative address 1101001b (0x69) is selected by pulling the SDO pin to 'V_{DDIO}'.

The timing specification for I²C of the BMG160 is given in Table 17:

Table 17: I²C timings

Parameter	Symbol	Condition	Min	Max	Units	
Clock Frequency	f _{SCL}			400	kHz	
SCL Low Period	t _{LOW}		1.3		μs	
SCL High Period	t _{HIGH}		0.6			
SDA Setup Time	t _{SUDAT}		0.1			
SDA Hold Time	t _{HDDAT}		0.0			
Setup Time for a repeated Start Condition	t _{SUSTA}		0.6			
Hold Time for a Start Condition	t _{HDSTA}		0.6			
Setup Time for a Stop Condition	t _{SUSTO}		0.6			
Time before a new Transmission can start	t _{BUF}		1.3			
Idle time between write accesses, normal mode,	t _{IDLE wacc nm}		2			μs
Idle time between write accesses, suspend mode	t _{IDLE wacc sm}		450			μs

Figure 14 shows the definition of the I²C timings given in Table 17:

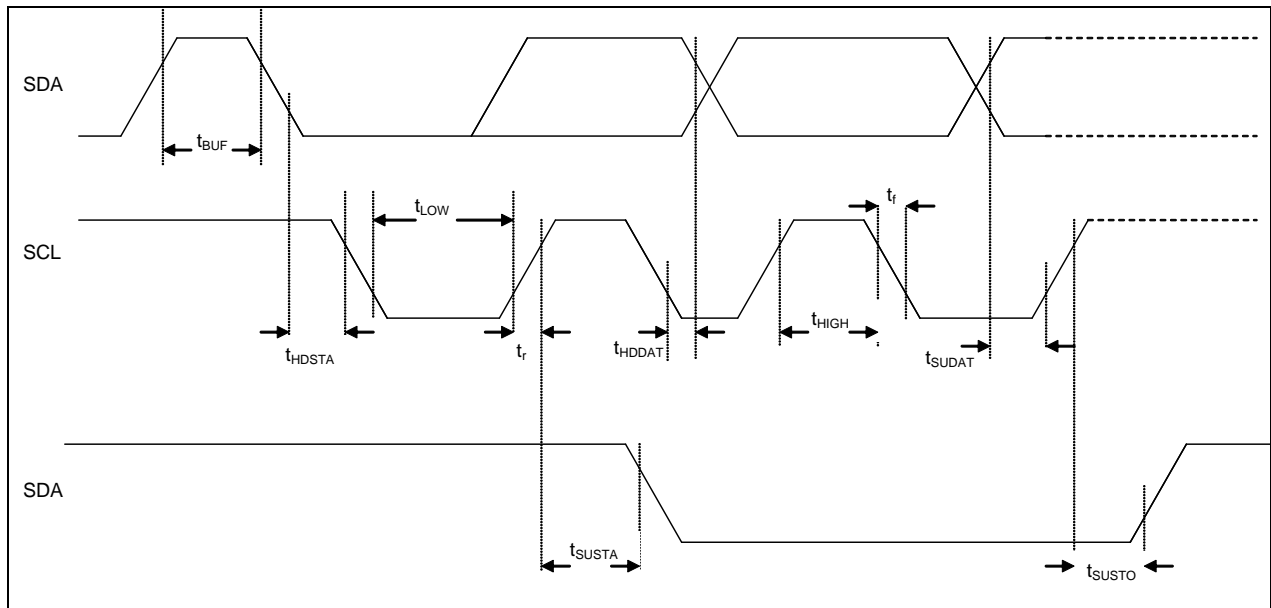


Figure 14: I²C timing diagram

The I²C protocol works as follows:

START: Data transmission on the bus begins with a high to low transition on the SDA line while SCL is held high (start condition (S) indicated by I²C bus master). Once the START signal is transferred by the master, the bus is considered busy.

STOP: Each data transfer should be terminated by a Stop signal (P) generated by master. The STOP condition is a low to HIGH transition on SDA line while SCL is held high.

ACK: Each byte of data transferred must be acknowledged. It is indicated by an acknowledge bit sent by the receiver. The transmitter must release the SDA line (no pull down) during the acknowledge pulse while the receiver must then pull the SDA line low so that it remains stable low during the high period of the acknowledge clock cycle.

In the following diagrams these abbreviations are used:

S	Start
P	Stop
ACKS	Acknowledge by slave
ACKM	Acknowledge by master
NACKM	Not acknowledge by master
RW	Read / Write

A START immediately followed by a STOP (without SCK toggling from logic “1” to logic “0”) is not supported. If such a combination occurs, the STOP is not recognized by the device.

I²C write access:

I²C write access can be used to write a data byte in one sequence.

The sequence begins with start condition generated by the master, followed by 7 bits slave address and a write bit (RW = 0). The slave sends an acknowledge bit (ACK = 0) and releases the bus. Then the master sends the one byte register address. The slave again acknowledges the transmission and waits for the 8 bits of data which shall be written to the specified register address. After the slave acknowledges the data byte, the master generates a stop signal and terminates the writing protocol.

Example of an I²C write access:

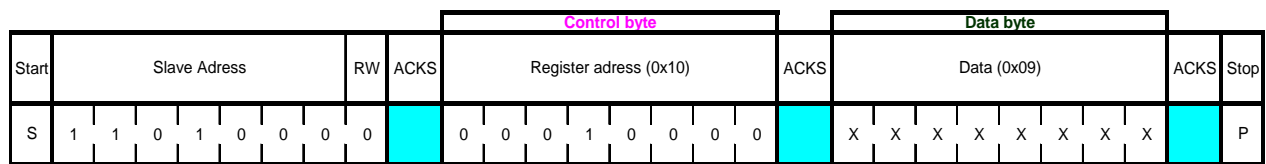


Figure 15: I²C write

I²C read access:

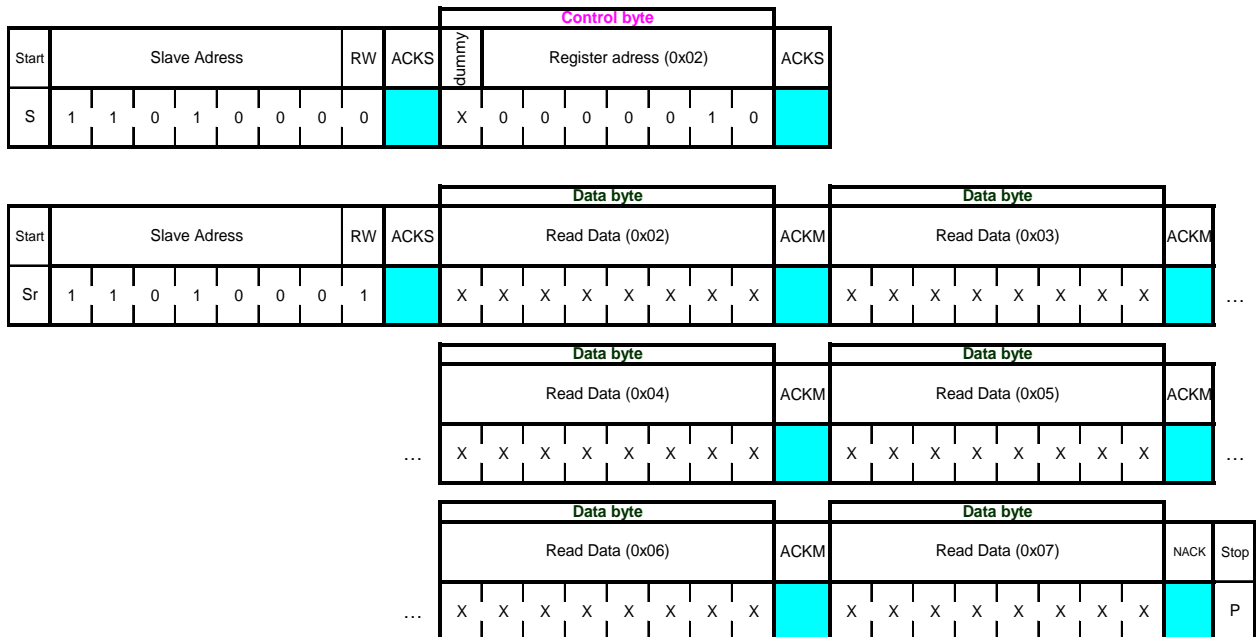
I²C read access also can be used to read one or multiple data bytes in one sequence.

A read sequence consists of a one-byte I²C write phase followed by the I²C read phase. The two parts of the transmission must be separated by a repeated start condition (Sr). The I²C write phase addresses the slave and sends the register address to be read. After slave acknowledges the transmission, the master generates again a start condition and sends the slave address together with a read bit (RW = 1). Then the master releases the bus and waits for the data bytes to be read out from slave. After each data byte the master has to generate an acknowledge bit (ACK = 0) to enable further data transfer. A NACKM (ACK = 1) from the master stops the data being transferred from the slave. The slave releases the bus so that the master can generate a STOP condition and terminate the transmission.

The register address is automatically incremented and, therefore, more than one byte can be sequentially read out. Once a new data read transmission starts, the start address will be set to the register address specified in the latest I²C write command. By default the start address is set at 0x00. In this way repetitive multi-bytes reads from the same starting address are possible.

In order to prevent the I²C slave of the device to lock-up the I²C bus, a watchdog timer (WDT) is implemented. The WDT observes internal I²C signals and resets the I²C interface if the bus is locked-up by the BMG160. The activity and the timer period of the WDT can be configured through the bits (0x34) *i2c_wdt_en* and (0x34) *i2c_wdt_sel*.

Writing '1' ('0') to (0x34) *i2c_wdt_en* activates (de-activates) the WDT. Writing '0' ('1') to (0x34) *i2c_wdt_se* selects a timer period of 1 ms (50 ms).

Example of an I²C read access:

 Figure 16: I²C multiple read

7.2.1 SPI and I²C Access Restrictions

In order to allow for the correct internal synchronisation of data written to the BMG160, certain access restrictions apply for consecutive write accesses or a write/read sequence through the SPI as well as I²C interface. The required waiting period depends on whether the device is operating in normal mode or suspend mode .

As illustrated in Figure 17 an interface idle time of at least 2 µs is required following a write operation when the device operates in normal mode.

In fast power-up mode idle time of least 450 µs is required.

In suspend mode, the only supported operations are reading and writing register (0x11) and (0x12) as well as writing to the (0x14) *softreset* register. Writing to other configuration registers while in suspend mode is not allowed.

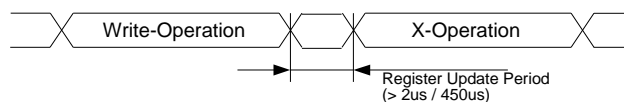


Figure 17: Post-Write Access Timing Constraints

8. Pin-out and connection diagram

8.1 Pin-out

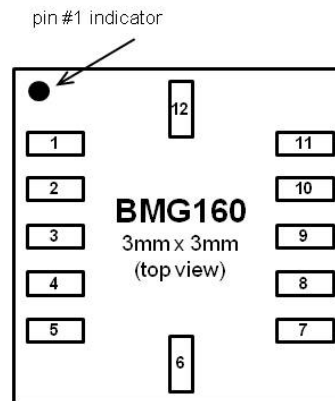


Figure 18: Pin-out top view

Table 18: Pin description

Pin#	Name	I/O Type	Description	Connect to		
				in SPI 4W	In SPI 3W	in I ² C
1	NC	--		GND	GND	GND
2	VDD	Supply	Power supply for analog & digital domain (1.62V ... 3.6V)	V _{DD}	V _{DD}	V _{DD}
3	GND	Ground	Ground for digital & analog	GND	GND	GND
4	INT1	Digital I/O	Interrupt pin 1 *	INT1	INT1	INT1
5	CSB	Digital in	Chip select for SPI mode	CSB	CSB	DNC (float)
6	PS	Digital in	Protocol select (GND = SPI, V _{DDIO} = I ² C)	GND	GND	V _{DDIO}
7	SCx	Digital in	SCK for SPI serial clock SCL for I ² C serial clock	SCK	SCK	SCL
8	SDO	Digital I/O	Serial data output in SPI Address select in I ² C mode see chapter 6.2	SDO	DNC (float)	GND for default addr.
9	SDx	Digital I/O	SDA serial data I/O in I ² C SDI serial data input in SPI 4W SDA serial data I/O in SPI 3W	SDI	SDA	SDA
10	VDDIO	Supply	Digital I/O supply voltage (1.2V ... 3.6V)	V _{DDIO}	V _{DDIO}	V _{DDIO}
11	GNDIO	Ground	Ground for I/O	GND	GND	GND
12	INT2	Digital I/O	Interrupt pin 2 *	INT2	INT2	INT2

* If INT1 and/or INT2 are not used, please do not connect them (DNC).

8.2 Connection diagram 4-wire SPI

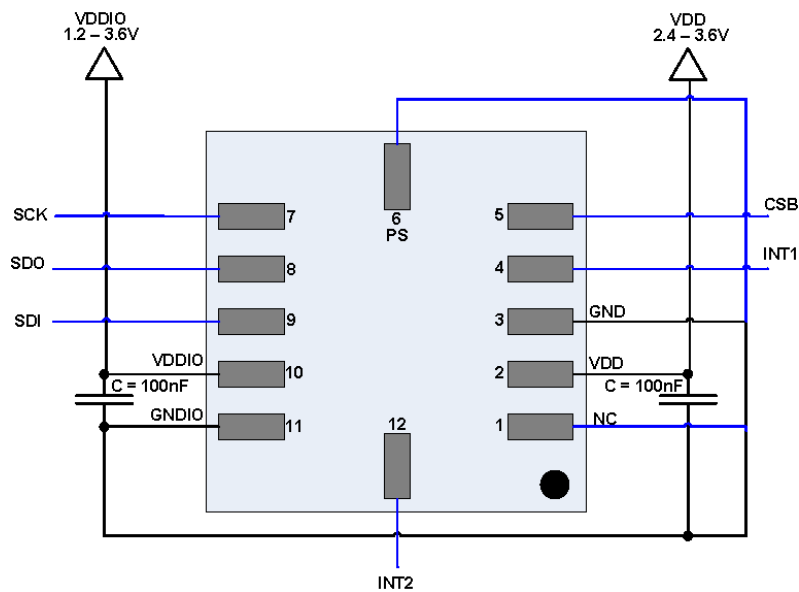


Figure 19: 4-wire SPI connection

In order to prevent noise on the supply pins VDD and VDDIO decoupling capacitors for the supply pins are mandatory. The decoupling capacitor should be at least 100nF at VDD and 100nF at VDDIO. The capacitors need to be placed as close to the supply pins (VDD and VDDIO) as possible. The ground connections GND should be separated as much as possible to prevent coupling from the noisy I/O supply pins into the sensitive analog supply pins.

8.3 Connection diagram 3-wire SPI

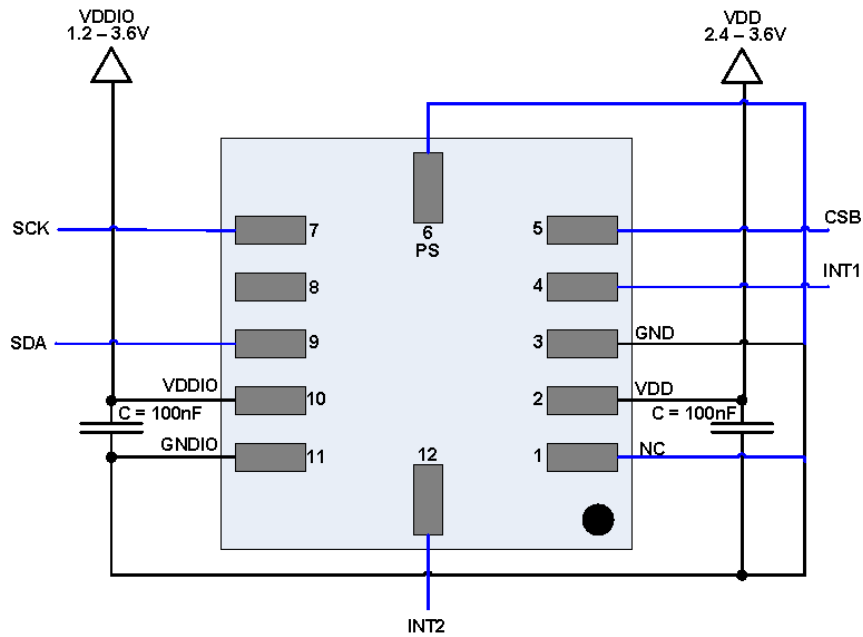


Figure 20: 3-wire SPI connection

8.4 Connection diagram I²C

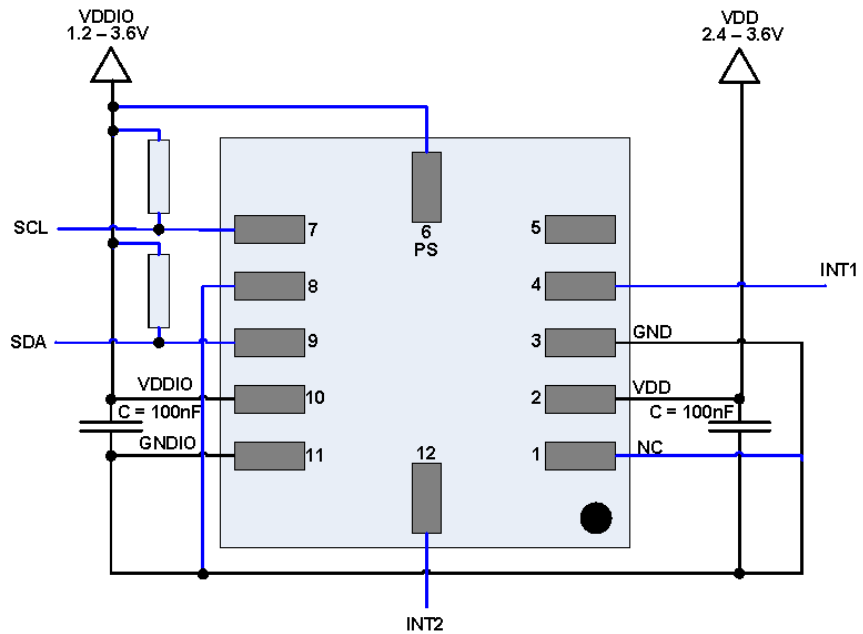


Figure 21: I²C connection

9. Package

9.1 Outline dimensions

The sensor housing is a standard LGA package. Its dimensions are the following.

Basic outline geometry is based on:

- Mold package footprint 3mm x 3mm (tolerance $\pm 0.1\text{mm}$)
- Height 0.95mm
- No. of leads 12
 - 11 used for electrical connection
 - 1 not used / reserved
- Lead pitch 0.5mm

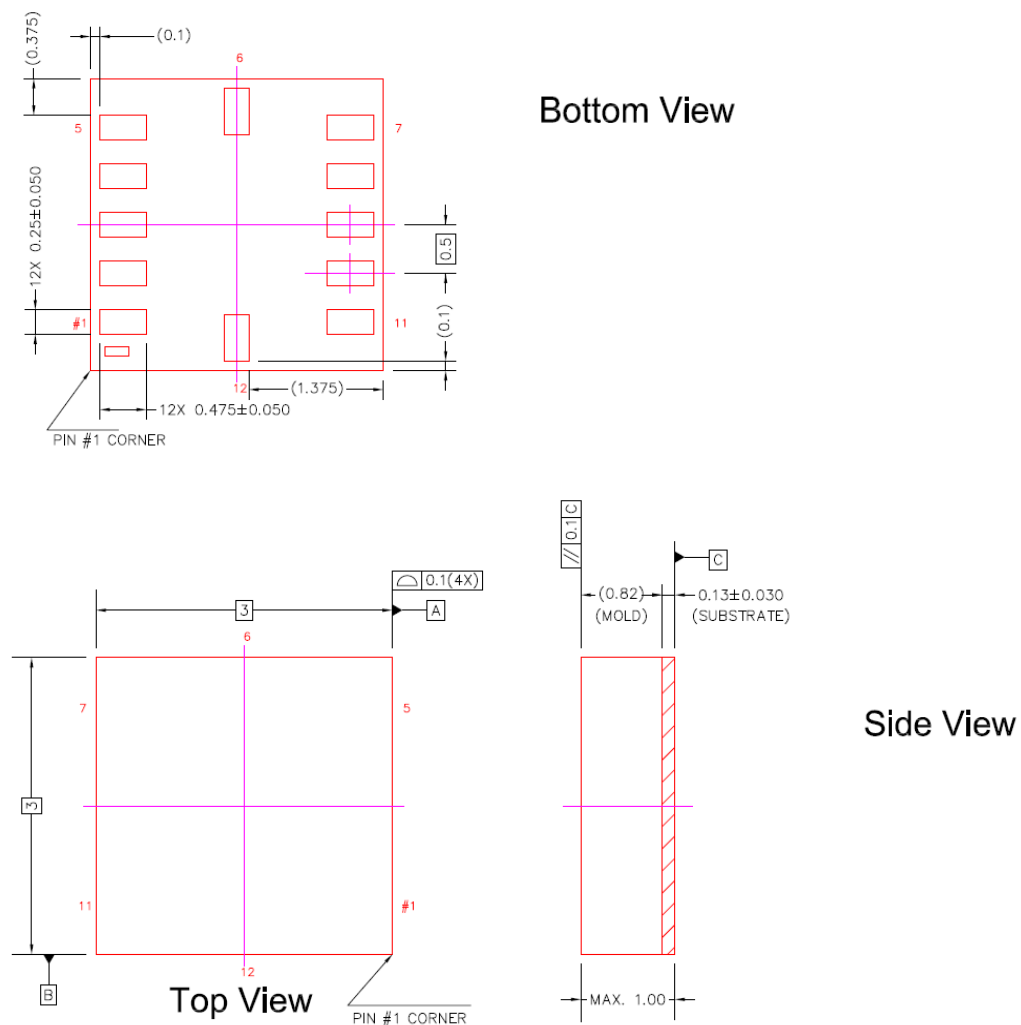


Figure 22: Package outline dimensions

9.2 Sensing axes orientation

If the sensor is rotated in the indicated directions, the corresponding channel will deliver a positive rate signal:

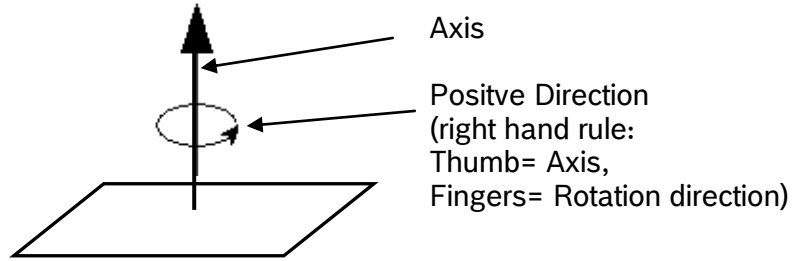


Figure 23

If the sensor is at rest the rate output for all axes is ideally zero (static case).

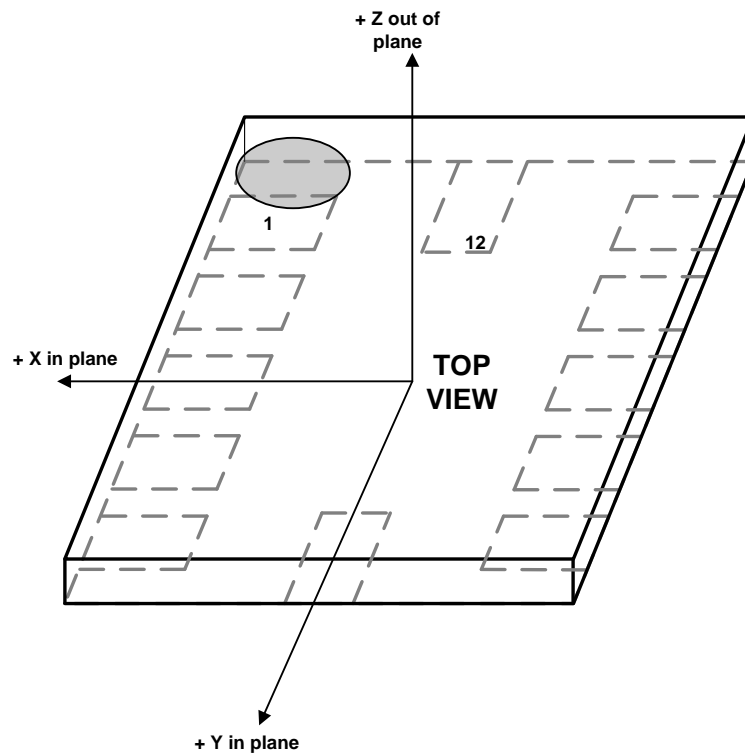


Figure 24: Orientation of sensing axis

9.3 Landing pattern recommendation

For the design of the landing patterns, we recommend the following dimensioning:

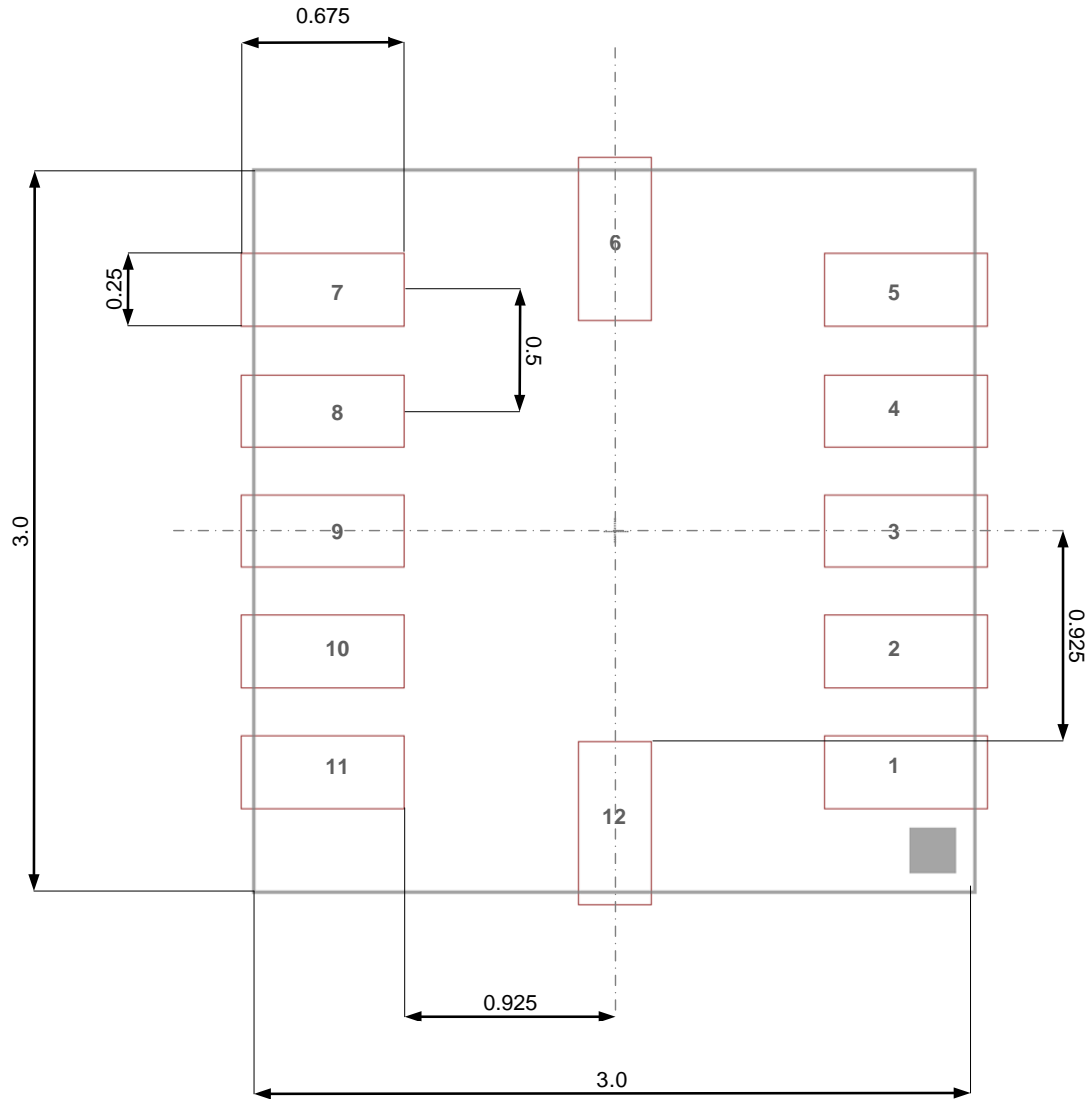


Figure 25: Landing pattern, dimensions are in mm

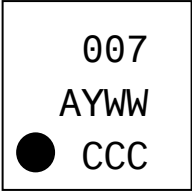
Same tolerances as given for the outline dimensions (chapter 9.1, fig. 22) should be assumed.



9.4 Marking

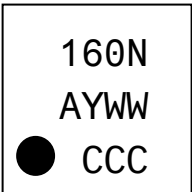
9.4.1 Mass production samples

Table 19: Marking of mass production samples

Labeling	Name	Symbol	Remark
	Product number	007	
	Subcon ID	A	Packaging sub-contractor identifier, coded alphanumerically. Symbol is an example here.
	Date code	YWW	Y: year, numerically coded: 9 = 2009, 0 = 2010, 1 = 2011, ... WW: Calendar week, numerical code
	Lot counter	CCC	
	Pin 1 identifier	●	--

9.4.2 Engineering samples

Table 20: Marking of engineering samples

Labeling	Name	Symbol	Remark
	Eng. sample ID	N	1 alphanumeric digit, fixed to identify engineering sample, N = “*” or “e” or “E”
	Subcon ID	A	Packaging sub-contractor identifier, coded alphanumerically. Symbol is an example here.
	Date code	YWW	Y: year, numerically coded: 9 = 2009, 0 = 2010, 1 = 2011, ... WW: Calendar week, numerical code
	Lot counter	CCC	
	Pin 1 identifier	●	--

9.5 Soldering guidelines

The moisture sensitivity level of the BMG160 sensors corresponds to JEDEC Level 1, see also

- IPC/JEDEC J-STD-020C "Joint Industry Standard: Moisture/Reflow Sensitivity Classification for non-hermetic Solid State Surface Mount Devices"
- IPC/JEDEC J-STD-033A "Joint Industry Standard: Handling, Packing, Shipping and Use of Moisture/Reflow Sensitive Surface Mount Devices"

The sensor fulfils the lead-free soldering requirements of the above-mentioned IPC/JEDEC standard, i.e. reflow soldering with a peak temperature up to 260°C.

Profile Feature	Pb-Free Assembly
Average Ramp-Up Rate ($T_{S_{max}}$ to T_p)	3° C/second max.
Preheat	
- Temperature Min ($T_{S_{min}}$)	150 °C
- Temperature Max ($T_{S_{max}}$)	200 °C
- Time ($t_{S_{min}}$ to $t_{S_{max}}$)	60-180 seconds
Time maintained above:	
- Temperature (T_L)	217 °C
- Time (t_L)	60-150 seconds
Peak/Classification Temperature (T_p)	260 °C
Time within 5 °C of actual Peak Temperature (t_p)	20-40 seconds
Ramp-Down Rate	6 °C/second max.
Time 25 °C to Peak Temperature	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

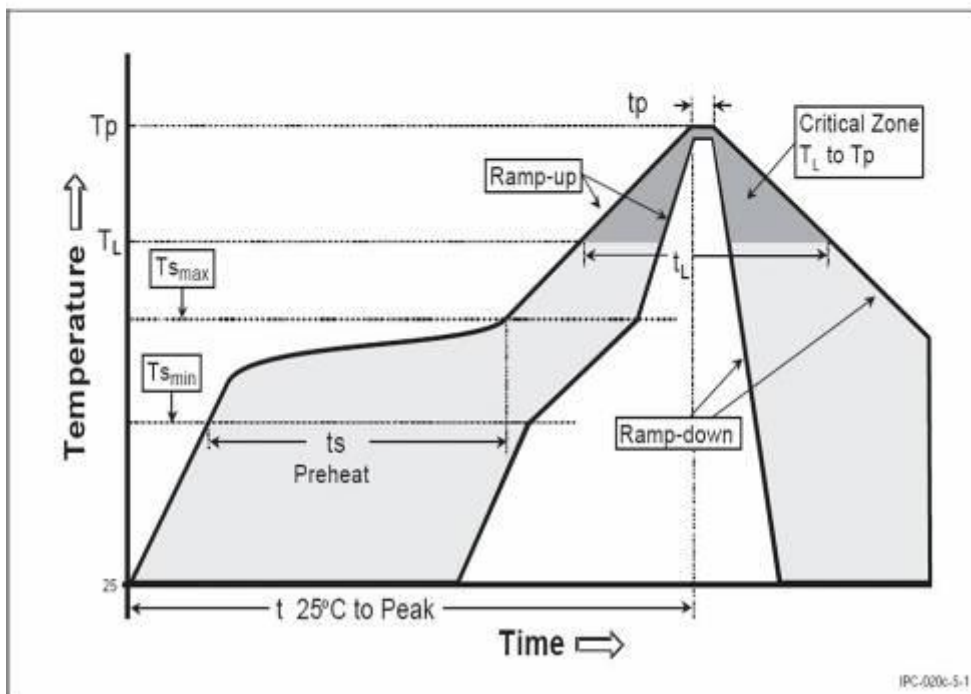


Figure 26: Soldering profile

9.6 Handling instructions

Micromechanical sensors are designed to sense angular rate with high accuracy even at low amplitudes and contain highly sensitive structures inside the sensor element. The MEMS sensor can tolerate mechanical shocks up to several thousand g's. However, these limits might be exceeded in conditions with extreme shock loads such as e.g. hammer blow on or next to the sensor, dropping of the sensor onto hard surfaces etc.

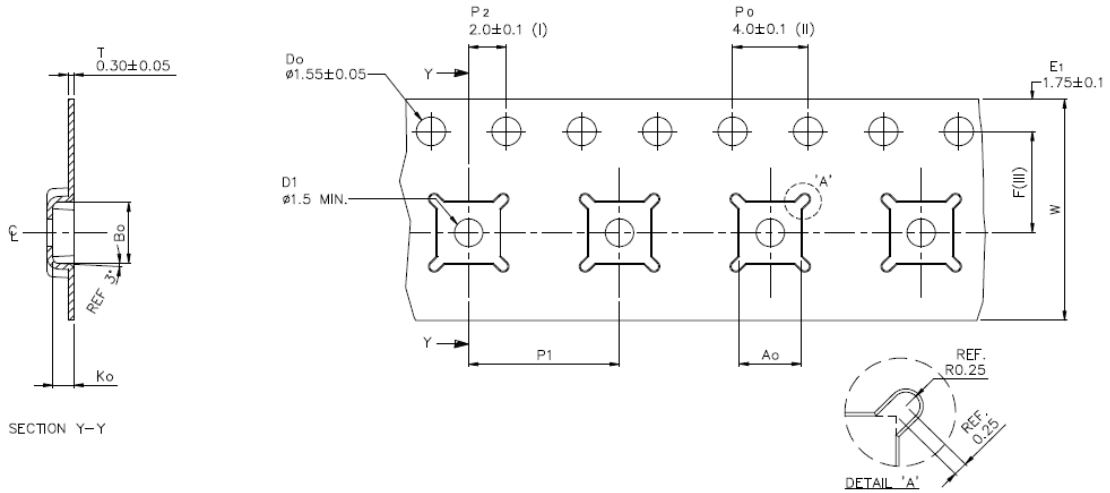
We recommend to avoid g-forces beyond the specified limits during transport, handling and mounting of the sensors in a defined and qualified installation process.

This device has built-in protections against high electrostatic discharges or electric fields (e.g. 2kV HBM); however, anti-static precautions should be taken as for any other CMOS component. Unless otherwise specified, proper operation can only occur when all terminal voltages are kept within the supply voltage range. Unused inputs must always be tied to a defined logic voltage level.

9.7 Tape and reel specification

The BMG160 is shipped in a standard cardboard box.
 The box dimension for 1 reel is: L x W x H = 35cm x 35cm x 5cm.
 BMG160 quantity: 5,000pcs per reel, please handle with care.

The following picture describes the dimensions of the tape used for shipping the BMG160 sensor device. The material of the tape is made of conductive polysterene (IV).



- (I) Measured from centreline of sprocket hole to centreline of pocket.
- (II) Cumulative tolerance of 10 sprocket holes is ± 0.20 .
- (III) Measured from centreline of sprocket hole to centreline of pocket.
- (IV) Other material available.

ALL DIMENSIONS IN MILLIMETRES UNLESS OTHERWISE STATED.

Figure 27: Tape and reel dimensions in mm

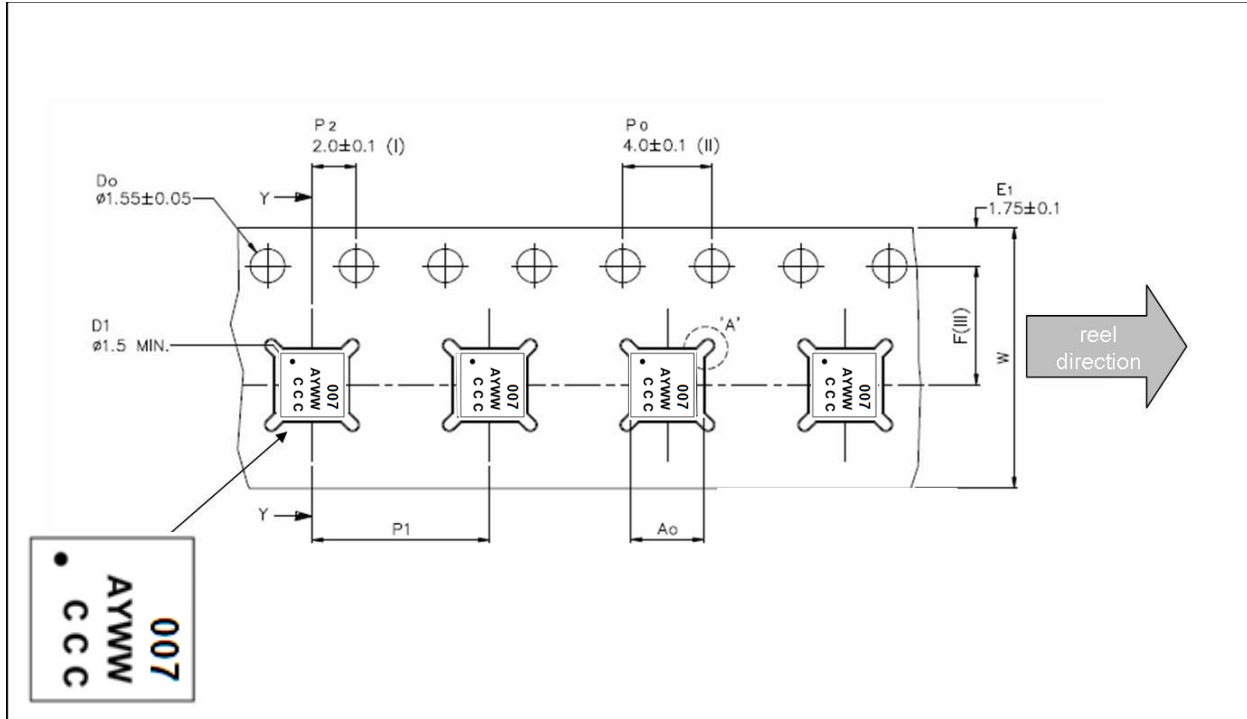
9.7.1 Orientation within the reel


Figure 28: Orientation of the BMG160 devices relative to the tape

9.7.2 Environmental safety

The BMG160 sensor meets the requirements of the EC restriction of hazardous substances (RoHS) directive, see also:

Directive 2002/95/EC of the European Parliament and of the Council of 8 September 2002 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

9.7.3 Halogen content

The BMG160 is halogen-free. For more details on the analysis results please contact your Bosch Sensortec representative.

9.7.4 Internal package structure

Within the scope of Bosch Sensortec's ambition to improve its products and secure the mass product supply, Bosch Sensortec qualifies additional sources (e.g. 2nd source) for the LGA package of the BMG160.

While Bosch Sensortec took care that all of the technical packages parameters are described above are 100% identical for all sources, there can be differences in the chemical content and the internal structural between the different package sources.

However, as secured by the extensive product qualification process of Bosch Sensortec, this has no impact to the usage or to the quality of the BMG160 product.

10. Legal disclaimer

10.1 Engineering samples

Engineering Samples are marked with an asterisk (*) or (e) or (E). Samples may vary from the valid technical specifications of the product series contained in this data sheet. They are therefore not intended or fit for resale to third parties or for use in end products. Their sole purpose is internal client testing. The testing of an engineering sample may in no way replace the testing of a product series. Bosch Sensortec assumes no liability for the use of engineering samples. The Purchaser shall indemnify Bosch Sensortec from all claims arising from the use of engineering samples.

10.2 Product use

Bosch Sensortec products are developed for the consumer goods industry. They may only be used within the parameters of this product data sheet. They are not fit for use in life-sustaining or security sensitive systems. Security sensitive systems are those for which a malfunction is expected to lead to bodily harm or significant property damage. In addition, they are not fit for use in products which interact with motor vehicle systems.

The resale and/or use of products are at the purchaser's own risk and his own responsibility. The examination of fitness for the intended use is the sole responsibility of the Purchaser.

The purchaser shall indemnify Bosch Sensortec from all third party claims arising from any product use not covered by the parameters of this product data sheet or not approved by Bosch Sensortec and reimburse Bosch Sensortec for all costs in connection with such claims.

The purchaser must monitor the market for the purchased products, particularly with regard to product safety, and inform Bosch Sensortec without delay of all security relevant incidents.

10.3 Application examples and hints

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11. Document history and modification

Rev. No	Chapter	Description of modification/changes	Date
0.1		Initial release (for internal use only)	
0.2		For internal use only	
0.3		Preliminary data sheet release	
0.4		Several Updates	
0.5		Several Updates	
0.6		Several Updates	
0.7		Several Updates	
0.8		Several Updates	
1.0	1, 4.2, 4.3.2, 4.6.2, 4.8, 6.2, 9.7.2	Final data sheet release	31 May 2013

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